Overview

HP EliteBook 860 16 inch G9 Notebook PC



- 1. Internal Microphones (2)
- 2. Ambient Light Sensor (Optional)
- 3. Webcam
- 4. Camera Shutter
- 5 IR Camera (Optional)
- 6. IR Camera LEDs (Optional)
- 7. Glass Clickpad
- 1. SuperSpeed USB 20Gbps is not available with Thunderbolt™ 4.

- Left
- 8. Smartcard Reader (Optional)
- 9. LED Indicator
- Thunderbolt[™] 4 with USB4 Type-C[®] 40Gbps signaling rate (USB Power Delivery, DisplayPort[™] 1.4)¹
- Thunderbolt[™] 4 with USB4 Type-C[®] 40Gbps signaling rate (USB Power Delivery, DisplayPort[™] 1.4)¹
- **12.** SuperSpeed USB Type-A 5Gbps signaling rate (USB 3.2 Gen 1)
- 13. HDMI 2.0b Port (Cable not included)



Overview



Right

- 1. Power Button Key
- 2. Audio Combo Jack
- **3.** SuperSpeed USB Type-A 5Gbps signaling rate (Charging) (USB 3.2 Gen 1)
- 4. Nano Security Lock Slot (Lock sold separately)
- 5. SIM Card Slot (Optional)
- 6. Touch Fingerprint Sensor (Select models)



QuickSpecs

Overview

At a Glance

- Preinstalled with Windows 11 versions or FreeDOS
- New premium ultraslim design with precision-crafted all-metal chassis for a premium look and feel
- 12th Generation Intel[®] Core™ i5, i7 U-series and i5, i7 P-series Processors up to fourteen-core
- New 16:10 ratio screen reduces the need to scroll by showing more vertical content than 16:9
- Optional ultrabright displays with HP Eye Ease, ambient light and ambient color sensors
- New 5MP camera¹ with HP Auto Frame² allows you around a little without losing viewers' attention during video calls
- New DDR5 memory and PCI Gen4 SSDs provide fast access to your work.
- Choice of displays:
 40.6 cm (16") diagonal WUXGA IPS Anti-Glare LED-backlit non-touch, 250 nits, 45% NTSC
 40.6 cm (16") diagonal WUXGA IPS Anti-Glare On-Cell LED-backlit touch, 250 nits, 45% NTSC
 40.6 cm (16") diagonal WUXGA IPS Anti-Glare LED-backlit non-touch, 400 nits, 100% sRGB with HP Eye Ease
 40.6 cm (16") diagonal WUXGA IPS Anti-Glare LED-backlit non-touch, 1000 nits, 100% sRGB with HP Sure View Reflect with HP Eye Ease
- Choose from 51Whr or 76Whr battery options
- HP Wolf Security for Business creates a hardware-enforced, always-on, resilient defense⁴
- Larger Clickpad surface for easier, more intuitive input
- Connectivity with optional Intel[®] 5000 5G/WWAN available world-wide, and Thunderbolt[™] Docking (Dock sold separately)
- Passed MIL-STD 810H tests⁵
- Supports fast charging (50% in 30 minutes) with no impact on battery recharge cycles⁶
- Designed to support all HP docking options including the HP Universal Dock G5

1. Optional feature that must be configured at the time of purchase.

2. HP Presence requires myHP application and Windows OS.

3. Requires Windows OS.

4. HP Wolf Security for Business requires Windows 10 and higher, includes various HP security features and is available on HP Pro, Elite, Workstation, and RPOS products. See product details for included security features and OS requirements.

5. MIL-STD 810H is not intended to demonstrate fitness of U.S. Department of Defense contract requirements or for military use. Test results are not a guarantee of future performance under these test conditions. Accidental damage requires an optional HP Accidental Damage Protection Care Pack.

6. SuperSpeed USB 20Gbps is not available with Thunderbolt™ 4.

NOTE: See important legal disclosures for all listed specs in their respective features sections.



PRODUCT NAME

HP EliteBook 860 16 inch G9 Notebook PC

OPERATING SYSTEMS

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FI	CIII	σια	lleu

Windows 11 Pro ¹ Windows 11 Pro Education ¹ Windows 11 Home - HP recommends Windows 11 Pro for business ¹ Windows 11 Home Single Language - HP recommends Windows 11 Pro for business ¹ Windows 11 Pro (Windows 11 Enterprise or Windows 10 Enterprise available with a Volume Licensing Agreement) ¹ Windows 11 Pro (preinstalled with Windows 10 Pro Downgrade) ^{1,2} FreeDOS

1. Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows is automatically updated and enabled. High speed internet and Microsoft account required. ISP fees may apply and additional requirements may apply over time for updates. See http://www.windows.com.

2. This system is preinstalled with Windows 10 Pro software and also comes with a license for Windows 11 Pro software and provision for recovery software. You may only use one version of the Windows software at a time. Switching between versions will require you to uninstall one version and install the other version. You must back up all data (files, photos, etc.) before uninstalling and installing operating systems to avoid loss of your data.

Processor 3,4,5,6,7 Cores of	Number		Threads	Thursda L3	Max Turbo Frequency		Base Frequency		Intel SIPP/vPro®	
	cores	P-cores	E-cores	Theaus	Cache	P- cores	E- cores	P- cores	E- cores	Enterprise
Intel® Core™ i7-1280P	14	6	8	20	24MB	4.8 GHz	3.6 GHz	1.8 GHz	1.3 GHz	Х
Intel® Core™ i7-1270P	12	4	8	16	18MB	4.8 GHz	3.5 GHz	2.2 GHz	1.6 GHz	Х
Intel® Core™ i7-1260P	12	4	8	16	18MB	4.7 GHz	3.4 GHz	2.1 GHz	1.5 GHz	
Intel [®] Core™ i5-1250P	12	4	8	16	12MB	4.4 GHz	3.3 GHz	1.7 GHz	1.2 GHz	Х
Intel® Core™ i5-1240P	12	4	8	16	12MB	4.4 GHz	3.3 GHz	1.2 GHz	1.3 GHz	
Intel® Core™ i7-1265U	10	2	8	12	12MB	4.8 GHz	3.6 GHz	1.8 GHz	1.3 GHz	Х
Intel® Core™ i7-1255U	10	2	8	12	12MB	4.7 GHz	3.5 GHz	1.7 GHz	1.2 GHz	
Intel® Core™ i5-1245U	10	2	8	12	12MB	4.4 GHz	3.3 GHz	1.2 GHz	1.2 GHz	х
Intel [®] Core™ i5-1235U	10	2	8	12	12MB	4.4 GHz	3.3 GHz	1.3 GHz	0.9 GHz	

PROCESSORS



3. Multicore is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. Intel's numbering, branding and/or naming is not a measurement of higher performance.

4. Processor speed denotes maximum performance mode; processors will run at lower speeds in battery optimization mode.

5. Intel[®] Turbo Boost performance varies depending on hardware, software and overall system configuration. See www.intel.com/technology/turboboost for more information.

6. In accordance with Microsoft's support policy, HP does not support the Windows 8 or Windows 7 operating system on products configured with Intel and AMD 7th generation and forward processors or provide any Windows 8 or Windows 7 drivers on http://www.support.hp.com.

7. Intel vPro[®] requires Windows 10 Pro 64 bit or higher, a vPro supported processor, vPro enabled chipset, vPro enabled wired LAN and/or Wi-Fi 6E WLAN and TPM 2.0. Some functionality requires additional 3rd party software in order to run. Features of vPro[®] Essentials and Enterprise vary. See http://intel.com/vpro

CHIPSET

Chipset is integrated with processor

GRAPHICS

Integrated Intel[®] Iris[®] X^e Graphics ⁸

Supports

Support HD decode, DX12, HDMI 2.0b, HDCP 2.3 ⁹

8. Intel[®] Iris[®] X^e Graphics capabilities require system to be configured with Intel[®] Core[™] i5 or i7 processors and dual channel memory. Intel[®] Iris[®] X^e Graphics with Intel[®] Core[™] i5 or 7 processors and single channel memory will only function as UHD graphics.

9. HDMI cable sold separately



DISPLAY

Non-Touch

40.64 cm (16") diagonal WUXGA Bent, anti-glare UWVA, 250 nits, 45% NTSC for 5MP camera (1920 x 1200)^{10,11} 40.64 cm (16") diagonal WUXGA Bent, anti-glare UWVA, 250 nits, 45% NTSC for 5MP+IR camera (1920 x 1200)^{10,11} 40.64 cm (16") diagonal WUXGA Bent, anti-glare UWVA, 250 nits, 45% NTSC for WWAN (1920 x 1200)^{10,11}

40.64 cm (16") diagonal WUXGA Bent, anti-glare UWVA, 250 nits, 45% NTSC for 5MP camera for WWAN (1920 x 1200) ^{10,11} 40.64 cm (16") diagonal WUXGA Bent, anti-glare UWVA, 250 nits, 45% NTSC for 5MP+IR camera for WWAN (1920 x 1200) ^{10,11} 40.64 cm (16") diagonal WUXGA Bent, anti-glare UWVA eDP1.2, micro-edge, 250 nits, 45% NTSC, Narrow Bezel (1920 x 1200) ^{10,11}

40.64 cm (16") diagonal WUXGA Bent, Low Blue Light, anti-glare UWVA eDP+PSR, 400 nits, 100% sRGB, Low Power, Ambient Light Sensor for 5MP Camera (1920 x 1200) with HP Eye Ease ^{10,11}

40.64 cm (16") diagonal WUXGA Bent, Low Blue Light, anti-glare UWVA eDP+PSR, 400 nits, 100% sRGB, Low Power, Ambient Light Sensor+Ambient Color Sensor for 5MP+IR Camera with (1920 x 1200) with HP Eye Ease ^{10,11}

40.64 cm (16") diagonal WUXGA Bent, Low Blue Light, anti-glare UWVA eDP+PSR, 400 nits, 100% sRGB, Low Power, Ambient Light Sensor+Ambient Color Sensor for 5MP Camera for WWAN (1920 x 1200) with HP Eye Ease ^{10,11}

40.64 cm (16") diagonal WUXGA Bent, Low Blue Light, anti-glare UWVA eDP1.3+PSR, 400 nits, 100% sRGB, Low Power,

Ambient Light Sensor+Ambient Color Sensor for 5MP+IR Camera for WWAN (1920 x 1200) with HP Eye Ease ^{10,11}

40.64 cm (16") diagonal WUXGA Bent, Low Blue Light, anti-glare UWVA eDP1.3+PSR, 1000 nits, 100% sRGB with HP Sure View Reflect integrated privacy screen, Ambient Light Sensor+Ambient Color Sensor for 5MP camera

(1920 x 1200) with HP Eye Ease ^{10,11,12,13}

40.64 cm (16") diagonal WUXGA Bent, Low Blue Light, anti-glare UWVA eDP1.3+PSR, 1000 nits, 100% sRGB with HP Sure View Reflect integrated privacy screen, Ambient Light Sensor+Ambient Color Sensor for 5MP+IR camera (1920 x 1200) with HP Eve Ease ^{10,11,12,13}

40.64 cm (16") diagonal WUXGA Bent, Low Blue Light, anti-glare UWVA eDP1.3+PSR, 1000 nits, 100% sRGB with HP Sure View Reflect integrated privacy screen, Ambient Light Sensor+Ambient Color Sensor for 5MP+IR camera for WWAN (1920 x 1200) with HP Eye Ease ^{10,11,12,13}

Touch

40.64 cm (16") diagonal WUXGA Bent, anti-glare UWVA, 250 nits, 45% NTSC for 5MP+IR camera Touch on Panel (1920 x 1200) ^{10,11,13}

40.64 cm (16") diagonal WUXGA Bent, anti-glare UWVA, 250 nits, 45% NTSC for 5MP+IR camera for WWAN Touch on Panel (1920 x 1200) ^{10,11,13}

DisplayPort™ 1.4

HDMI 2.0 Support resolution up to 4K @60 Hz ⁹

Displays support

Supports dual display through the dock

Display Size (Diagonal)

16" 40.64 cm (16")

9. HDMI cable sold separately

10. HD content required to view HD images.

11. Resolutions are dependent upon monitor capability, and resolution and color depth settings.

12. HP Sure View Reflect integrated privacy screen is an optional feature that must be configured at purchase and is designed to function in landscape orientation.



13. Actual brightness will be lower with touchscreen or HP Sure View.

DOCKING (Sold Separately)

Docking station model #1	HP Thunderbolt Dock G2		
Docking station model #2	HP USB-C Dock G5		
Docking station model #3	HP USB-C/A Universal Dock G2		
Docking station model #4	HP Thunderbolt 120W G4 Dock		
Docking station model #5	HP Thunderbolt 280W G4 Dock		
For additional aftermarket options and docking specs please see page 45.			

STORAGE AND DRIVES

Primary M.2 Storage

2 TB PCIe[®] Gen4x4 NVMe[™] M.2 SSD TLC ¹⁴ 1 TB PCIe[®] Gen4x4 NVMe[™] M.2 SSD TLC ^{14,15} 512 GB PCIe[®] Gen4x4 NVMe[™] M.2 SSD TLC ¹⁴ 512 GB PCIe[®] Gen4x4 NVMe[™] SED TLC OPAL2¹⁴ 512 GB PCIe[®] Gen4x4 NVMe[™] M.2 SSD ¹⁴ 256 GB PCIe[®] Gen4x4 NVMe[™] SED TLC OPAL2 ¹⁴ 256 GB PCIe[®] Gen4x4 NVMe[™] SED TLC OPAL2 ¹⁴ 256 GB PCIe[®] NVMe[™] Value M.2 SSD ¹⁴

14. For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 30 GB (for Windows 10 and 11) is reserved for system recovery software.
15. Available only to HK (Hong Kong), TW (Taiwan) and CN (China).

MEMORY

Maximum Memory 64GB DDR5-4800 ¹⁶

Memory

```
64GB DDR5-4800 (2x32GB) <sup>16</sup>
32GB DDR5-4800 (2x16GB) <sup>16</sup>
32GB DDR5-4800 (1x32GB) <sup>16</sup>
16GB DDR5-4800 (2x8GB) <sup>16</sup>
16GB DDR5-4800 (1x16GB) <sup>16</sup>
8GB DDR5-4800 (1x8GB) <sup>16</sup>
```

Memory Slots

2 SODIMM DDR5 SODIMMS, system runs at 4800 Supports Dual Channel Memory



16. Due to the non-industry standard nature of some third-party memory modules, we recommend HP branded memory to ensure compatibility. If you mix memory speeds, the system will perform at the lower memory speed.

NETWORKING/COMMUNICATIONS

WLAN

Intel® AX211 Wi-Fi6E+Bluetooth® 5.3 M.2 160MHz CNVi vPro Wireless Card ^{17,18,9} Intel® AX211 Wi-Fi6E+Bluetooth® 5.3 M.2 160MHz CNVi non-vPro Wireless Card ^{17,19}

WWAN

Intel[®] 5000 5G Solution WWAN ^{20,21} Intel[®] XMM 7560 R+ LTE-Advanced Pro WWAN (Cat 16) ²⁰

NFC

Near Field Communication (NFC) module ²²² HP Module with NXP NFC Controller NPC300 I2C NCI

Miracast

Native Miracast Support ²³

17. Wi-Fi 6E requires a Wi-Fi 6E router, sold separately, to function in the 6GHz band. Availability of public wireless access points limited. Wi-Fi 6E is backwards compatible with prior 802.11 specs. And available in countries where Wi-Fi 6E is supported.

18. For full Intel[®] vPro[™] functionality, Windows, a vPro supported processor, vPro enabled chipset, vPro enabled WLAN card and discrete TPM 2.0 are required. See https://www.intel.com/content/www/us/en/architecture-and-technology/vpro/vpro-platform-general.html

19. Wi-Fi 6E is designed to support gigabit data rate when transferring files between two devices connected to the same router. Requires a wireless router, sold separately, that supports 80MHz and higher channels.

20. WWAN module is an optional feature, requires factory configuration and requires separately purchased service contract. Check with service provider for coverage and availability in your area. Connection speeds will vary due to location, environment, network conditions, and other factors. 4G LTE not available on all products, in all regions.

21. Intel 5G module is optional and must be configured at the factory. Module designed for 5G NR NSA (non-standalone) networks as carriers deploy Evolved-Universal Terrestrial Radio Access New Radio Dual Connectivity (ENDC) with both 100Mhz of 5G NR and LTE channel bandwidth, using 256QAM 4x4 as defined by 3GPP. Module requires activation and separately purchased service contract. Check with service provider for coverage and availability in your area. Data connection, upload and download speeds will vary due to network, location, environment, network conditions, and other factors. Backwards compatible to 4G LTE and 3G HSPA technologies. 5G module planned to be available in select platforms and select countries, where carrier supported.

22. Sold separately or as an optional feature.

23. Miracast is a wireless technology your PC can use to project your screen to TVs, projectors, and streaming.



AUDIO/MULTIMEDIA

Audio

Audio by Bang & Olufsen 2 Integrated stereo speakers Discrete Amplifiers Integrated dual array microphone

Speaker Power

1W/8ohm Per speaker

Camera

5 MP camera ²² 5 MP+IR camera ²²

Sensors

ALS (ambient light sensor) Magnetometer Hall Sensor Gyro Accelerometer HP Tamper Lock ²⁴

22. Sold separately or as an optional feature.

24. HP Tamper Lock must be enabled by the customer or your administrator.



KEYBOARDS/POINTING DEVICES/BUTTONS & FUNCTION KEYS

Keyboard

HP Premium Keyboard, spill resistant, Backlit keyboard and DuraKeys²⁵ HP Premium Keyboard, spill resistant, Non-Backlit keyboard and DuraKeys HP Premium Keyboard, spill resistant, Backlit keyboard and DuraKeys Privacy

Pointing Device

Clickpad with multi-touch gesture support, taps enabled as default Microsoft Precision Touchpad Default Gestures Support

Function Keys

ESC: system information F1 - Display Switching F2 - Blank or Privacy F3 - Brightness Down F4 - Brightness Up F5 - Audio Mute F6 - Volume Down F7 - Volume Up F8 - Mic Mute F9 - Blank or Backlit Toggle F10 - Insert F11 - Airplane Mode F12 - HP Programmable Key Print Screen Power Button (with LED) delete home end pq up pg dn **Hidden Function Keys**

Fn+R - Break Fn+S - Sys Rq Fn+C - Scroll Lock

25. Backlit keyboard is an optional feature.



SOFTWARE AND SECURITY

Software

HP Quick Touch HP Quick Drop ²⁶ HP Easy Clean²⁷ HP PC Hardware Diagnostics Windows myHP HP Smart Support ²⁸ HP Connection Optimizer HP Hotkey Support HP Support Assistant ²⁹ HP Notifications HP Privacy Settings HP Power Manager Buy Microsoft Office (Sold separately)

Manageability Features

HP Image Assistant Gen5 (download) HP Manageability Integration Kit (download) ³⁰ HP Client Management Script Library (download) HP Driver Packs (download) HP Cloud Recovery ³¹ HP Client Catalog (download)

NOTE: To enhance brightness, level go to the Intel[®] Graphics Command Center app, click on System and turn off the Display Power Savings function.

Security Management

HP Wolf Security of Business ³² includes: HP Sure Click ³³ HP Sure Sense ³⁴ HP Sure Run Gen5 ³⁵ HP Sure Recover Gen5 ³⁶ HP Sure Start Gen7 ³⁷ HP Tamper Lock HP Sure Admin ³⁸ HP Client Security Manager Gen7 ³⁹

BIOS

HP BIOSphere Gen6 ⁴⁰ HP Secure Erase ⁴¹ Absolute Persistence Module ⁴² HP DriveLock & Automatic DriveLock BIOS Update via Network HP Wake on WLAN HP Fingerprint Sensor ⁴³ Secured-Core PC Enable ⁴⁴ TPM 2.0 Embedded Security Chip (Common Criteria EAL4+ Certified) (FIPS 140-2 Level 2 Certified)



Security

ТРМ

Model: Infineon SLB9672VU2.0 Version: 15.21 Revision: TPM 2.0 FIPS 140-2 Compliant: Yes

Smartcard Reader

Model number: Alcor AU9560 FIPS 201 Compliant: Yes

IPv6 Support

Yes

FirstNet Certified

Yes

Is the BIOS on this notebook ISO/IEC 19678:2015 (formerly NIST 800-147) compliant?: Yes UEFI version: 2.7

Class: 3

26. HP Quick Drop requires Internet access and Windows 10 or higher PC preinstalled with HP QuickDrop app and either an Android device (phone or tablet) running Android 7 or higher with the Android HP QuickDrop app, and /or an iOS device (phone or tablet) running iOS 12 or higher with the iOS HP QuickDrop app.

27. HP Easy Clean requires Windows 10 RS3 and higher and will disable the keyboard, touchscreen, and clickpad only. Ports are not disabled. See user guide for cleaning instructions.

28. HP Smart Support automatically collects the telemetry necessary upon initial boot of the product to deliver device-level configuration data and health insights and is available preinstalled on select products, thru HP Factory Configuration Services; or it can be downloaded. For more information about how to enable HP Smart Support or for download, please visit http://www.hp.com/smart-support.

29. HP Support Assistance requires Windows and Internet Access

30. HP Manageability Integration Kit can be downloaded from

http://www8.hp.com/us/en/ads/clientmanagement/overview.html.

31. HP Cloud Recovery is available for Z by HP, HP Elite and Pro desktops and laptops PCs with Intel[®] or AMD processors and requires an open, wired network connection. **NOTE:** You must back up important files, data, photos, videos, etc. before use to avoid loss of data. Detail please refer to: https://support.hp.com/us-en/document/c05115630.

32. HP Wolf Security for Business requires Windows 10 or higher, includes various HP security features and is available on HP Pro, Elite, RPOS and Workstation products. See product details for included security features and OS requirement.

33. HP Sure Click requires Windows 10 Pro or higher or Enterprise. See https://bit.ly/2PrLT6A_SureClick for complete details.
34. HP Sure Sense is available on select HP PCs with Windows 10 Pro, Windows 10 Enterprise, Windows 11 Pro, or Windows 11 Enterprise OS.

35. HP Sure Run Gen5 is available on select HP PCs and requires Windows 10 and higher.

36. HP Sure Recover Gen5 with Embedded Reimaging is an optional feature which requires Windows 10 and higher must be configured at purchase. You must back up important files, data, photos, videos, etc. before use to avoid loss of data. Network based recovery using Wi-Fi is only available on PCs with Intel Wi-Fi Module.

37. HP Sure Start Gen7 is available on select HP PCs and requires Windows 10 and higher.

38. HP Sure Admin requires Windows 10 or higher, HP BIOS, HP Manageability Integration Kit from

http://www.hp.com/go/clientmanagement and HP Sure Admin Local Access Authenticator smartphone app from the Android or Apple store.

39. HP Client Security Manager Gen7 requires Windows and is available on the select HP Elite and Pro PCs.

40. HP BIOSphere Gen6 features may vary depending on the platform and configuration.



41. HP Secure Erase for the methods outlined in the National Institute of Standards and Technology Special Publication 800-88 "Clear" sanitation method. HP Secure Erase does not support platforms with Intel[®] Optane[™].

42. Absolute firmware module is shipped turned off and can only be activated with the purchase a license subscription and full activation of the software agent. License subscriptions can be purchased for terms ranging multiple years. Service is limited, check with Absolute for availability outside the U.S. Certain conditions apply. For full details visit: https://www.absolute.com/about/legal/agreements/absolute/

43. HP Fingerprint sensor is an optional feature that must be configured at purchase.

44. Secured-Core PC Enable requires an Intel[®] vPro[®], AMD Ryzen[™] Pro processor or Qualcomm[®] processor with SD850 or higher and requires 8 GB or more system memory. Secured-core PC is enabled from the factory.



POWER

Power Supply

HP Smart 65 W USB Type-C adapter ⁴⁵ HP Smart 45 W USB Type-C adapter ⁴⁵ HP 100W+10W Slim USB-C+USB-A AC power adapter ⁴⁵

Battery

HP Long Life 3-cell, 51 Wh Polymer ^{46,47} HP Long Life 6-cell, 76 Wh Polymer ^{46,47} Compliant with UL 1642 Standard

Power Cord

3-wire plug - 1m 2-wire plug - 1m

Battery Life

Up to 12 hours 15 minutes (51Whr) 28W⁴⁸ Up to 12 hours 30 minutes (51Whr) 15W⁴⁸ Up to 18 hours 15 minutes (76Whr) 28W⁴⁸ Up to 19 hours (76Whr) 15W⁴⁸

45. Availability may vary by country.

46. Battery is internal and not replaceable by customer. Serviceable by warranty.

47. Actual battery Watt-hours (Wh) will vary from design capacity. Battery capacity will naturally decrease with shelf life, time, usage, environment, temperature, system configuration, loaded apps, features, power management settings and other factors.

48. MM18 battery life will vary depending on various factors including product model, configuration, loaded applications, features, use, wireless functionality, and power management settings. The maximum capacity of the battery will naturally decrease with time and usage. See www.bapco.com for additional details.

WEIGHTS & DIMENSIONS

Product Weight- 51 Wh ⁴⁹ Starting at 3.88 lb Starting at 1.76 kg

Product Dimensions (W x D x H)

14.12 x 9.88 x 0.76 in 35.87 x 25.1 x 1.92 cm

49. Weight will vary by configuration. Does not include power adapter.



PORTS/SLOTS

- 2 Thunderbolt[™] 4 with USB4 Type-C[®] 40Gbps signaling rate (USB Power Delivery, DisplayPort[™] 1.4) ⁵⁰
- 2 Super Speed USB Type-A 5Gbps signaling rate (1 charging) (USB 3.2 Gen 1)
- 1 HDMI 2.0 ⁹
- 1 Headphone/microphone combo jack
- 1 Nano Security Lock Slot (Lock sold separately)
- 1 Smartcard reader (Optional)
- 1 nano SIM card slot
- 9. HDMI cable sold separately
- 50. SuperSpeed USB 20Gbps is not available with Thunderbolt™ 4.



SERVICE AND SUPPORT

1-year warranty and 90 day software limited warranty options depending on country. Batteries have a default one year limited warranty except for HP Long Life batteries which will follow the one or three year warranty of the platform. Refer to http://www.hp.com/support/batterywarranty/ for additional battery information. On-site service and extended coverage is also available. HP Care Pack Services are optional extended service contracts that go beyond the standard limited warranties. To choose the right level of service for your HP product, use the HP Care Pack Services Lookup Tool at: http://www.hp.com/go/cpc.⁵¹

51. HP Care Packs are sold separately. Service levels and response times for HP Care Packs may vary depending on your geographic location. Service starts on date of hardware purchase. Restrictions and limitations apply. For details, visit www.hp.com/go/cpc. HP services are governed by the applicable HP terms and conditions of service provided or indicated to Customer at the time of purchase. Customer may have additional statutory rights according to applicable local laws, and such rights are not in any way affected by the HP terms and conditions of service or the HP Limited Warranty provided with your HP Product.



SYSTEM UNIT

JIJIENUNII	
Stand-Alone Power Requirements (AC Power)	Type-C Adapter
Nominal Operating Voltage Average Operating Power	AC 20V
Integrated graphics	Yes
Discrete Graphics	N/A
Max Operating Power	UMA<100W
Temperature	
Operating	32° to 95° F (0° to 35° C)
Non-operating	41° to 95° F (5° to 35° C) (writing optical)
Relative Humidity	
Operating	10% to 90%, non-condensing
Non-operating	5% to 95%, 101.6° F (38.7° C) maximum wet bulb temperature
Shock	
Operating	40 G, 2 ms, half-sine
Non-operating	200 G, 2 ms, half-sine
Random Vibration	
Operating	0.75 grams
Non-operating	1.50 grams
Altitude (unpressurized) Operating	-50 to 10,000 ft (-15.24 to 3,048 m)
Non-operating	-50 to 40,000 ft (-15.24 to 12,192 m)
Planned Industry Standard	-50 10 40,000 11 (-15.24 10 12,152 11)
Certifications	
Regulatory Model Number	HSN-145C-6
UL	Yes
CSA	Yes
FCC Compliance	Yes
ENERGY STAR [®]	Certified ⁵²
EPEAT [®]	EPEAT [®] Gold in the United States ⁵³
ICES	Yes
Australia /	Yes
NZ A-Tick Compliance	Yes
CCC	Yes
Japan VCCI Compliance KC	Yes Yes
BSMI	Yes
CE Marking Compliance	Yes
BNCI or BELUS	Yes
CIT	Yes
GOST	Yes
Saudi Arabian Compliance (ICCP)	Yes
SABS	Yes



52. Configurations of the HP EliteBook 860 G9 that are ENERGY STAR[®] qualified are identified as HP EliteBook 860 G9 ENERGY STAR on HP websites and on http://www.energystar.gov.

53. Based on US EPEAT[®] registration according to IEEE 1680.1-2018 EPEAT[®]. EPEAT[®] status varies by country. Visit http://www.epeat.net for more information.

DISPLAYS

NOTE: All specifications represent the typical specifications provided by HP's component manufacturers; actual performance may vary either higher or lower.

1. Actual brightness will be lower with touchscreen or HP Sure View.

16.0 in WUXGA	Outline Dimensions (W x H x D)	350.380 x 226.170 (max)
	Active Area	344.678 x 215.424 (typ)
UWVA LED NTSC NB2X 250	Weight	390 (max)
eDP 1.2 w/o PSR 45 bent LCD Panel	Diagonal Size	16 inch
	Thickness	3.0 / 5.0 (max)
	Interface	eDP 1.2
	Surface Treatment	Anti-Glare
	Touch Enabled	No
	Contrast Ratio	1000:1(typ)
	Refresh Rate	60 Hz
	Brightness	250 nits
	Pixel Resolution - Format	1920 x 1280 (WUXGA)
	Backlight	WLED
	Pixel Resolution	RGB
	Color Gamut Coverage	NTSC 45%
	Color Depth	6
	Viewing Angle	UWVA 89/89/89/89
	Low Blue Light	No
	Power Consumption (W, EBL@	2.70 (max) / 2.40 (max)

16.0 in WUXGA (1920 x 1200) Anti-Glare UWVA LED NTSC NB2X 250 TOP eDP 1.2 w/o PSR 45 bent LCD Panel	Outline Dimensions (W x Active Area Weight Diagonal Size Thickness
	Thickness Interface Surface Treatment
	Touch Enabled

Contrast Ratio

Refresh Rate

Brightness

H x D) 350.680 x 226.470 (max) 344.680 x 215.420 (typ) 400 (max) 16 3.0 / 5.0 (max) eDP 1.2 Anti-Glare Yes¹ 1000:1(typ) 60 Hz 250 nits ⁰



QuickSpecs

Technical Specifications

Pixel Resolution - Format	1920 x 1280 (WUXGA)
Backlight	WLED
Pixel Resolution	RGB
Color Gamut Coverage	NTSC 45%
Color Depth	8
Viewing Angle	UWVA 89/89/89/89
Low Blue Light	No
Power Consumption (W, EBL@ 150nits max/ 200nits max)	2.70 (max) / 2.40 (max)

16.0 in WUXGA (1920 x 1200) Anti-Glare UWVA WLED+LBL sRGB NB2X 400 eDP 1.4+PSR2 Low-Power 100 bent LCD Panel

Outline Dimensions (W x H x D)	350.680 x 226.470 (max)
Active Area	344.678 x 215.424 (typ)
Weight	330 (max)
Diagonal Size	16
Thickness	2.6 / 4.6 (max)
Interface	eDP 1.4
Surface Treatment	Anti-Glare
Touch Enabled	No
Contrast Ratio	1000:1(typ)
Refresh Rate	60 Hz
Brightness	400 nits
Pixel Resolution - Format	1920 x 1200 (WUXGA)
Backlight	WLED
Pixel Resolution	RGB
Color Gamut Coverage	sRGB 100%
Color Depth	8
Viewing Angle	UWVA 89/89/89/89
Low Blue Light	Yes
Power Consumption (W, EBL@ 150nits max/ 200nits max)	1.60 (max) / 1.95 (max)

16.0 in WUXGA (1920 x 1200) Anti-Glare UWVA WLED+LBL sRGB NB2Y 1000 eDP 1.3+PSR 100 PrivacyG4 Plus bent LCD Panel

Outline Dimensions (W x H x D)	349.980 x 225.420 (max)
Active Area	344.680 x 215.420 (typ)
Weight	310 (max)
Diagonal Size	16
Thickness	2.2 / 3.9 (max)
Interface	eDP 1.3
Surface Treatment	Anti-Glare
Touch Enabled	No



Contrast Ratio	1500:1 (typ)
Refresh Rate	60 Hz
Brightness	1000 nits
Pixel Resolution - Format	1920 x1200 (WUXGA)
Backlight	WLED
Pixel Resolution	RGB
Color Gamut Coverage	sRGB 100%
Color Depth	8
Viewing Angle	UWVA 85/85/85/85
Low Blue Light	Yes
Power Consumption (W, EBL@ 150nits max/ 200nits max)	N/A



STORAGE AND DRIVES

For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 30 GB (for Windows 10 and 11) is reserved for system recovery software.

SSD 256GB 2280 PCIe-4x4	Form Factor	M.2 2280		
NVMe Three Layer Cell	Capacity	256GB		
	NAND Type	TLC		
	Height	0.09 in (2.3 mm)		
	Width	0.87 in (22 mm)		
	Weight	0.02 lb (10 g)		
	Interface	PCIe NVMe Gen4X4		
	Maximum Sequential Read	4000 MB/s ±20%		
	Maximum Sequential Write	2000 MB/s ±20%		
	Logical Blocks	500,118,192		
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]		
	Features	Pyrite 2.0; TRIM; L1.2		
SSD 512GB 2280 PCIe-4x4	Form Factor	M.2 2280		
NVMe Three Layer Cell	Capacity	512GB		
	NAND Type	TLC		
	Height	0.09 in (2.3 mm)		
	Width	0.87 in (22 mm)		
	Weight	0.02 lb (10 g)		
	Interface	PCIe NVMe Gen4X4		
	Maximum Sequential Read	6400 MB/s ±20%		
	Maximum Sequential Write	3500 MB/s ±20%		
	Logical Blocks	1,000,215,215		
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]		
	Features	Pyrite 2.0; TRIM; L1.2		
SSD 1TB 2280 PCIe-4x4	Form Factor	M.2 2280		
NVMe Three Layer Cell	Capacity	1TB		
	NAND Type	TLC		
	Height	0.09 in (2.3 mm)		
	Width	0.87 in (22 mm)		
	Weight	0.02 lb (10 g)		
	Interface	PCIe NVMe Gen4X4		
	Maximum Sequential Read	6400 MB/s ±20%		
	Maximum Sequential Write	5000 MB/s ±20%		



	Logical Blocks	2,000,409,264
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]
	Features	Pyrite 2.0; TRIM; L1.2
SSD 2TB 2280 PCIe-4x4 NVMe Three Layer Cell	Form Factor	M.2 2280
Norie Three Layer Cett	Capacity	2TB
	NAND Type	TLC
	Height	0.09 in (2.3 mm)
	Width	0.87 in (22 mm)
	Weight	0.02 lb (10 g)
	Interface	PCIe NVMe Gen4X4
	Maximum Sequential Read	6400 MB/s ±20%
	Maximum Sequential Write	5000 MB/s ±20%
	Logical Blocks	4,000,797,360
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]
	Features	Pyrite 2.0; TRIM; L1.2
256GB PCIe-4x4 2280 NVME	Form Factor	M.2 2280
Self Encrypted OPAL2	Capacity	256GB
Three Layer Cell Solid State	NAND Type	TLC
Drive	Height	0.09 in (2.3 mm)
	Width	0.87 in (22 mm)
	Weight	0.02 lb (10 g)
	Interface	PCIe NVMe Gen4X4
	Maximum Sequential Read	4000 MB/s ±20%
	Maximum Sequential Write	2000 MB/s ±20%
	Logical Blocks	500,118,192
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]
	Features	TCG Opal 2.0; TRIM; L1.2



Self Encrypted OPAL2 Three Layer Cell Solid State Drive AND Type TLC Height OO' to 20 to (10 g) Interface Naximum Sequential Read G400 MK/s ±20% Maximum Sequential Write G400 MK/s ±20% Maximum Sequential Read S5D 512GB 2280 PCIe NVMe Form Factor G400 MK/s ±20% Maximum Sequential Read S5D 512GB 2280 PCIe NVMe Form Factor G400 MK/s ±20% Maximum Sequential Read S5D 512GB 2280 PCIe NVMe Form Factor G400 MK/s ±20% Maximum Sequential Read S5D 512GB 2280 PCIe NVMe Form Factor G400 MK/s ±20% Maximum Sequential Read S5D 512GB 2280 PCIe NVMe Form Factor G400 MK/s ±20% Maximum Sequential Read S5D 512GB 2280 PCIe NVMe Form Factor G400 MK/s ±20% Maximum Sequential Read S5D 512GB 2280 PCIe NVMe Form Factor G400 MK/s ±20% Maximum Sequential Read S5D 512GB 2280 PCIe NVMe Form Factor G400 MK/s ±20% Maximum Sequential Read S5D 512GB 2280 PCIe NVMe Form Factor G400 MK/s ±20% Maximum Sequential Read S5D 512GB 2280 PCIe NVMe Form Factor G400 MK/s ±20% Maximum Sequential Read S5D 512GB 2280 PCIe NVMe Form Factor G400 MK/s ±20% Maximum Sequential Read S5D 512GB 2280 PCIe NVMe Form Factor G400 MK/s ±20% Maximum Sequential Read S5D 512GB 2280 PCIe NVMe Form Factor G400 MK/s ±20% Maximum Sequential Read	512GB PCIe-4x4 2280 NVME	Form Factor	M.2 2280		
Three Layer Cell Solid State Drive NAND Type TLC Height 0.09 in (2.3 mm) Width 0.87 in (22 mm) Width 0.71 in (22 mm) Width 0.71 in (22 mm) Weight 0.72 ib (10 g) Interface PCIe NVMe Gen4X4 Maximum Sequential Read 6400 MB/s ±20% Maximum Sequential Write 3500 MB/s ±20% Logical Blocks 1,000,215,215 Operating Temperature 32* to 158* f0* to 70*C) [ambient temp] Features TCC Value Capacity Value Capacity Width 0.87 in (22 mm) Weight 0.02 lb (10 g) Interface PCIe NVMe Gen3X4 Maximum Sequential Read 1500 MB/s ±20% Logical Blocks 500,118,192 Operating Temperature 32* to 158* f0* to 70*C) [ambient temp] Features Pyrite 2.0; TRIM; L1.2			512GB		
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Maximum Sequential Read6400 MB/s ±20%Maximum Sequential Write3500 MB/s ±20%Logical Blocks1,000,215,215Operating Temperature32° to 158°F (0° to 70°C) [ambient temp]FeaturesTCG Opal 2.0; TRIM; L1.2SSD 256G8 2280 PCIe NVMeForm FactorKallerM.2 2280Capacity256 G8MAND TypeTLCHeight0.09 in (2.3 mm)Width0.87 in (22 mm)Weight0.02 lb (10 g)InterfacePCie NVMe Gen3X4Maximum Sequential Read1500 MB/s ±20%Logical Blocks500,118,192Operating Temperature32° to 158°F (0° to 70°C) [ambient temp]FeaturesVriteSSD 512G8 2280 PCIe NVMeForm FactorNAND TypeTLCHeight0.09 in (2.3 mm)Width500 MB/s ±20%Logical Blocks500,118,192Operating Temperature32° to 158°F (0° to 70°C) [ambient temp]FeaturesTLCNAND TypeTLCHeight0.09 in (2.3 mm)Width0.87 in (22 mm)Width0.87 in (22 mm)Width0.09 in (2.3 mm)Width0.02 lb (10 g)InterfacePCIe NVMe Gen3X4Maximum Sequential Read1500 MB/s ±20%Maximum Sequential Read1500 MB/s ±20%Ligical Blocks0.002 lb (10 g)InterfacePCIe NVMe Gen3X4Maximum Sequential Read1500 MB/s ±20%Ligical Blocks1500 MB/s ±20%Ligical Blocks <td< th=""><th></th><th>-</th><th>_</th></td<>		-	_		
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NAND TypeL300bNAND TypeTLCHeight0.09 in (2.3 mm)Width0.87 in (22 mm)Weight0.02 lb (10 g)InterfacePCle NVMe Gen3X4Maximum Sequential Read1500 MB/s ±20%Logical Blocks500,118,192Operating Temperature32° to 158°F (0° to 70°C) [ambient temp]FeaturesPyrite 2.0; TRIM; L1.2SSD 512GB 2280 PCLe NVMEForm FactorValueCapacitySSD 512GB 2280 PCLe NVMEForm FactorWidth0.99 in (2.3 mm)Width0.99 in (2.3 mm)Width0.87 in (22 mm)Width0.87 in (22 mm)Wight0.02 lb (10 g)InterfacePCle NVME Gen3X4Maximum Sequential Read1500 MB/s ±20%Maximum Sequential Write750 MB/s ±20%Logical Blocks1,000,215,215Operating Temperature32° to 158°F (0° to 70°C) [ambient temp]	SSD 256GB 2280 PCIe NVMe	Form Factor	M.2 2280		
Height0.09 in (2.3 mm)Width0.87 in (22 mm)Weight0.02 lb (10 g)InterfacePCle NVMe Gen3X4Maximum Sequential Read1500 MB/s ±20%Maximum Sequential Write750 MB/s ±20%Logical Blocks500,118,192Operating Temperature32° to 158°F (0° to 70°C) [ambient temp]FeaturesPyrite 2.0; TRIM; L1.2SSD 512GB 2280 PCle NVMeForm FactorValueM.2 2280Capacity512 GBNAND TypeTLCHeight0.09 in (2.3 mm)Width0.87 in (22 mm)Weight0.02 lb (10 g)InterfacePCle NVMe Gen3X4Maximum Sequential Read1500 MB/s ±20%Logical Blocks1,000,215,215Operating Temperature32° to 158°F (0° to 70°C) [ambient temp]	Value	Capacity	256 GB		
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InterfacePCIe NVMe Gen3X4Maximum Sequential Read1500 MB/s ±20%Maximum Sequential Write750 MB/s ±20%Logical Blocks500,118,192Operating Temperature32° to 158°F (0° to 70°C) [ambient temp]FeaturesPyrite 2.0; TRIM; L1.2SSD 512GB 2280 PCIe NVMeForm FactorM.2 2280Capacity512 GBNAND TypeTLCHeight0.09 in (2.3 mm)Width0.87 in (22 mm)Weight0.02 lb (10 g)InterfacePCle NVMe Gen3X4Maximum Sequential Read1500 MB/s ±20%Maximum Sequential Write750 MB/s ±20%Logical Blocks1,000,215,215Operating Temperature32° to 158°F (0° to 70°C) [ambient temp]		Width	0.87 in (22 mm)		
Maximum Sequential Read1500 MB/s ±20%Maximum Sequential Write750 MB/s ±20%Logical Blocks500,118,192Operating Temperature32° to 158°F (0° to 70°C) [ambient temp]FeaturesPyrite 2.0; TRIM; L1.2SSD 512GB 2280 PCIe NVMForm FactorM.2 2280Capacity512 GBNAND TypeTLCHeight0.09 in (2.3 mm)Width0.87 in (22 mm)Width0.02 lb (10 g)InterfacePCIe NVMe Gen3X4Maximum Sequential Read1500 MB/s ±20%Maximum Sequential Write750 MB/s ±20%Logical Blocks1,000,215,215Operating Temperature32° to 158°F (0° to 70°C) [ambient temp]		Weight	0.02 lb (10 g)		
Maximum Sequential Write750 MB/s ±20%Logical Blocks500,118,192Operating Temperature32° to 158°F (0° to 70°C) [ambient temp]FeaturesPyrite 2.0; TRIM; L1.2SSD 512GB 2280 PCIe NVMeForm FactorM.2 2280Capacity512 GBNAND TypeTLCHeight0.09 in (2.3 mm)Width0.87 in (22 mm)Weight0.02 lb (10 g)InterfacePCIe NVMe Gen3X4Maximum Sequential Read1500 MB/s ±20%Logical Blocks1,000,215,215Operating Temperature32° to 158°F (0° to 70°C) [ambient temp]		Interface	PCIe NVMe Gen3X4		
Logical Blocks500,118,192Operating Temperature32° to 158°F (0° to 70°C) [ambient temp]FeaturesPyrite 2.0; TRIM; L1.2SSD 512GB 2280 PCIe NVMPForm FactorValueM.2 2280Capacity512 GBNAND TypeTLCHeight0.09 in (2.3 mm)Width0.87 in (22 mm)Weight0.02 lb (10 g)InterfacePCle NVMe Gen3X4Maximum Sequential Read1500 MB/s ±20%Logical Blocks1,000,215,215Operating Temperature32° to 158°F (0° to 70°C) [ambient temp]		Maximum Sequential Read	1500 MB/s ±20%		
Operating Temperature Features32° to 158°F (0° to 70°C) [ambient temp] Pyrite 2.0; TRIM; L1.2SSD 512GB 2280 PCIe NVMe ValueForm FactorM.2 2280Capacity512 GBNAND TypeTLCHeight0.09 in (2.3 mm)Width0.87 in (22 mm)Weight0.02 lb (10 g)InterfacePCle NVMe Gen3X4Maximum Sequential Read1500 MB/s ±20%Logical Blocks1,000,215,215Operating Temperature32° to 158°F (0° to 70°C) [ambient temp]		Maximum Sequential Write	750 MB/s ±20%		
FeaturesPyrite 2.0; TRIM; L1.2SSD 512GB 2280 PCle NVMe ValueForm FactorM.2 2280Capacity512 GBNAND TypeTLCHeight0.09 in (2.3 mm)Width0.87 in (22 mm)Weight0.02 lb (10 g)InterfacePCle NVMe Gen3X4Maximum Sequential Read1500 MB/s ±20%Logical Blocks1,000,215,215Operating Temperature32° to 158°F (0° to 70°C) [ambient temp]		Logical Blocks	500,118,192		
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ValueCapacity512 GBNAD TypeTCHeight0.9 in (2.3 mm)With0.3 in (2.2 mm)Wight0.2 lo (1.0 g)InterfacePC NVMc Gen3X4Maximum Sequential Read150 MB/s ± 20%Maximum Sequential Write1000,215,215Logical Blocks0.9 in (2.5 sc) (0.0 g)WithSci (0.5 sc) (0.0 g)Matimum Sequential Write1000,215,215Matimum Sequential Write1000,215,215		Features	Pyrite 2.0; TRIM; L1.2		
ValueCapacity512 GBNAND TypeTCHeight0.9 in (2.3 mm)With0.3 in (2.2 mm)With0.2 lo (1.0 g)InterfacePC NVMc Gen3X4Maximum Sequential Read1500 MS/s ± 20%Maximum Sequential Write1000,2 15,2 15Logical Blocks1000,2 15,2 15Marting Temperature2 % 00,2 15,2 15	SSD 512GB 2280 PCIe NVMe	Form Factor	M.2 2280		
NAND TypeTLCHeight0.09 in (2.3 mm)Width0.87 in (22 mm)Weight0.02 lb (10 g)InterfacePCle NVMe Gen3X4Maximum Sequential Read1500 MB/s ±20%Maximum Sequential Write750 MB/s ±20%Logical Blocks1,000,215,215Operating Temperature32° to 158°F (0° to 70°C) [ambient temp]					
Height0.09 in (2.3 mm)Width0.87 in (22 mm)Weight0.02 lb (10 g)InterfacePCle NVMe Gen3X4Maximum Sequential Read1500 MB/s ±20%Maximum Sequential Write750 MB/s ±20%Logical Blocks1,000,215,215Operating Temperature32° to 158°F (0° to 70°C) [ambient temp]					
Width0.87 in (22 mm)Weight0.02 lb (10 g)InterfacePCle NVMe Gen3X4Maximum Sequential Read1500 MB/s ±20%Maximum Sequential Write750 MB/s ±20%Logical Blocks1,000,215,215Operating Temperature32° to 158°F (0° to 70°C) [ambient temp]			0.09 in (2.3 mm)		
InterfacePCIe NVMe Gen3X4Maximum Sequential Read1500 MB/s ±20%Maximum Sequential Write750 MB/s ±20%Logical Blocks1,000,215,215Operating Temperature32° to 158°F (0° to 70°C) [ambient temp]		Width	0.87 in (22 mm)		
Maximum Sequential Read1500 MB/s ±20%Maximum Sequential Write750 MB/s ±20%Logical Blocks1,000,215,215Operating Temperature32° to 158°F (0° to 70°C) [ambient temp]		Weight	0.02 lb (10 g)		
Maximum Sequential Write750 MB/s ±20%Logical Blocks1,000,215,215Operating Temperature32° to 158°F (0° to 70°C) [ambient temp]		Interface	PCIe NVMe Gen3X4		
Logical Blocks1,000,215,215Operating Temperature32° to 158°F (0° to 70°C) [ambient temp]		Maximum Sequential Read	1500 MB/s ±20%		
Logical Blocks1,000,215,215Operating Temperature32° to 158°F (0° to 70°C) [ambient temp]		Maximum Sequential Write	750 MB/s ±20%		
Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]		Logical Blocks			
		-	32° to 158°F (0° to 70°C) [ambient temp]		
			Pyrite 2.0; TRIM; L1.2		



SSD 1 TB 2280 PCIe NVMe	Form Factor	M.2 2280
Value ¹	Capacity	1TB
	NAND Type	TLC
	Interface	PCIe NVMe Gen4X4
	Maximum Sequential Read	Up to 3200 MB/s ±20%
	Maximum Sequential Write	Up to 2700 MB/s ±20%
	Logical Blocks	2,000,409,264
	Features	Pyrite 2.0; TRIM; L1.2
1. Available only to HK (Hor	ig Kong), TW (Taiwan) and CN (Chin	a).



NETWORKING/COMMUNICATIONS

Intel® AX211 Wi-Fi 6E + Bluetooth® 5.3 M.2	Wireless LAN Standards	IEEE 802.11a IEEE 802.11b
160MHz CNVi WLAN vPro®		IEEE 802.11g
Wireless Card ¹		IEEE 802.11n
		IEEE 802.11ac
		IEEE 802.11ax
		IEEE 802.11d
		IEEE 802.11e
		IEEE 802.11h
		IEEE 802.11i
		IEEE 802.11k
		IEEE 802.11r
		IEEE 802.11v
	Interoperability	Wi-Fi certified
	Frequency Band	•802.11b/g/n/ax
		2.402 – 2.482 GHz
		•802.11a/n/ac/ax
		4.9 – 4.95 GHz (Japan)
		5.15 – 5.25 GHz 5.25 – 5.35 GHz
		5.47 – 5.725 GHz
		5.825 – 5.850 GHz
		5.955 – 6.415 GHz
		6.435 – 6.515 GHz
		6.535 – 6.875 GHz
		6.895 – 7.115 GHz
	Data Rates	• 802.11b: 1, 2, 5.5, 11 Mbps
		• 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
		• 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
		• 802.11n: max 300Mbps
		• 802.11ac : 1733Mbps
		• 802.11ax : max 2.4Gbps
	Modulation	Direct Sequence Spread Spectrum
		OFDM, BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM, 1024QAM
	Security ²	 IEEE and WiFi compliant 64 / 128 bit WEP encryption for a/b/g mode only
		AES-CCMP: 128 bit in hardware
		• 802.1x authentication
		 WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES. WPA2 certification
		• WPA3 certification
		• IEEE 802.11i
		• WAPI
	Network Architecture	Ad-hoc (Peer to Peer)
	Models	Infrastructure (Access Point Required)
	Roaming	IEEE 802.11 compliant roaming between access points
	-	
	Output Power ³	• 802.11b : +17dBm minimum



Power Consumption	 802.11n HT40(7 802.11n HT20(7 802.11n HT40(7 802.11ac VHT8 802.11ac VHT1 802.11ac VHT1 802.11ax HE40 802.11ax HE80 802.11ax HE16 Transmit mode Receive mode 1 Idle mode (PSP) 	Bm minimum 2.4GHz) : +14dBm minimum 2.4GHz) : +13dBm minimum 5GHz) : +14dBm minimum 5GHz) : +13dBm minimum 0(5GHz) : +10dBm minimum 60(5GHz) : +10dBm minimum (2.4GHz) : +10dBm minimum 0(5GHz) : +10dBm minimum 2.0 W .6 W 180 mW (WLAN Associated) W (WLAN unassociated) idby 10mW
Power Management	ACPI and PCI Exp	ress compliant power management t power saving mode
Receiver Sensitivity ⁴	 802.11b, 11Mb 802.11a/g, 6Mb 802.11a/g, 54M 802.11n, MCSO 802.11n, MCSO 802.11ac, MCSO 802.11ac, MCSO 802.11ac, MCSO 802.11ac, MCSO 802.11ax, MCSO 802.11ax, MCSO 	s: -93.5dBm maximum ps: -84dBm maximum pps: -86dBm maximum lbps: -72dBm maximum 7: -67dBm maximum 5: -64dBm maximum 0(VHT80) : -84dBm maximum 0(VHT80) : -59dBm maximum 0(VHT160) : -59dBm maximum 11(HE40): -57dBm maximum 11(HE80): -54dBm maximum 11(HE160): -53.5dBm maximum
Antenna type	High efficiency antenna with spatial diversity, mounted in the display enclosure Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth communications	
Form Factor	PCI-Express M.2	MiniCard
Dimensions	1. Type 2230 : 2.	3 x 22.0 x 30.0 mm
Weight	1. Туре 2230 : 2.8	Bg
Operating Voltage	3.3v +/- 9%	
Temperature	Operating Non-operating	14° to 158° F (–10° to 70° C) –40° to 176° F (–40° to 80° C)
Humidity	Operating Non-operating	10% to 90% (non-condensing) 5% to 95% (non-condensing)
Altitude	Operating Non-operating	0 to 10,000 ft (3,048 m) 0 to 50,000 ft (15,240 m)
LED Activity	LED Amber – Rad	lio OFF; LED OFF – Radio ON
vith Bluetooth 4.0/4.1/4.2/5.0	/5.1/5.2/5.3 Wire	eless Card

HP Integrated Module with Bluetooth 4.0/4.1/4.2/5.0/5.1/5.2/5.3 Wireless Card



Bluetooth Specification	4.0/4.1/4.2/5.0/5.1/5.2/5.3 Compliant
Frequency Band	2402 to 2480 MHz
Number of Available Channels	Legacy: 0~79 (1 MHz/CH) BLE : 0~39 (2 MHz/CH)
Signaling Data Rate	Legacy: 3 Mbps data rate; throughput up to 2.17 Mbps BLE : 1 Mbps data rate; throughput up to 0.2 Mbps Legacy : Synchronous Connection Oriented links up to 3, 64 kbps, voice channels Legacy : Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)
Transmit Power	The Bluetooth component shall operate as a Class II Bluetooth device with a maximum transmit power of + 9.5 dBm for BR and EDR.
Power Consumption	Peak (Tx): 330 mW Peak (Rx): 230 mW Selective Suspend: 17 mW
Bluetooth Software Supported Link Topology	Microsoft Windows Bluetooth Software
Power Management	Microsoft Windows ACPI, and USB Bus Support
Certifications	FCC (47 CFR) Part 15C, Section 15.247 & 15.249
Power Management Certifications	ETS 300 328, ETS 300 826 Low Voltage Directive IEC950 UL, CSA, and CE Mark
Bluetooth Profiles Supported	BT4.1-ESR 5/6/7 Compliance LE Link Layer Ping LE Dual Mode LE Link Layer LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels Train Nudging & Interlaced Scan BT4.2 ESR08 Compliance LE Secure Connection- Basic/Full LE Privacy 1.2 –Link Layer Privacy LE Privacy 1.2 –Link Layer Privacy LE Privacy 1.2 –Extended Scanner Filter Policies LE Data Packet Length Extension FAX Profile (FAX) Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP) Advanced Audio Distribution Profile (A2DP) BT5.2 ESR9/10 Compliance LE Advertisement Extensions Channel Selection Algo Limited High Duty Cycle Non-Connectable Advertising 2Mbps LE LE Long Range



1. Wi-Fi 6E requires a Wi-Fi 6E router, sold separately, to function in the 6GHz band. Availability of public wireless access points limited. Wi-Fi 6E is backwards compatible with prior 802.11 specs. And available in countries where Wi-Fi 6E is supported. Wi-Fi 6E is designed to support gigabit data rate when transferring files between two devices connected to the same router. Requires a wireless router, sold separately, that supports 80MHz and higher channels.

2. Check latest software/driver release for updates on supported security features.

3. The FCC has declared as of September 1, 2014 products that utilize passive scanning on channel 12/13 and are capable of transmitting must fully comply with requirements of 15.247 or otherwise disable those channels.

4. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).

Intel® AX211 Wi-Fi 6E + Bluetooth® 5.3 M.2 160MHz CNVi WLAN non- vPro® Wireless Card ¹	Wireless LAN Standards	IEEE 802.11a IEEE 802.11b IEEE 802.11g IEEE 802.11n IEEE 802.11ac IEEE 802.11ax IEEE 802.11d IEEE 802.11e IEEE 802.11h IEEE 802.11h IEEE 802.11i IEEE 802.11k IEEE 802.11r
	Interoperability	Wi-Fi certified
	Frequency Band	•802.11b/g/n/ax 2.402 – 2.482 GHz •802.11a/n/ac/ax 4.9 – 4.95 GHz (Japan) 5.15 – 5.25 GHz 5.25 – 5.35 GHz 5.47 – 5.725 GHz 5.825 – 5.850 GHz 5.955 – 6.415 GHz 6.435 – 6.515 GHz 6.535 – 6.875 GHz 6.895 – 7.115 GHz
	Data Rates	 802.11b: 1, 2, 5.5, 11 Mbps 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps 802.11n: max 300Mbps 802.11ac : 1733Mbps 802.11ax : max 2.4Gbps
	Modulation	Direct Sequence Spread Spectrum OFDM, BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM, 1024QAM
	Security ²	 IEEE and WiFi compliant 64 / 128 bit WEP encryption for a/b/g mode only AES-CCMP: 128 bit in hardware

QuickSpecs

Technical Specifications 802.1x authentication • WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES. WPA2 certification WPA3 certification • IEEE 802.11i • WAPI **Network Architecture** Ad-hoc (Peer to Peer) Models Infrastructure (Access Point Required) Roaming IEEE 802.11 compliant roaming between access points **Output Power³** • 802.11b : +17dBm minimum • 802.11g : +16dBm minimum 802.11a : +17dBm minimum • 802.11n HT20(2.4GHz) : +14dBm minimum 802.11n HT40(2.4GHz): +13dBm minimum 802.11n HT20(5GHz) : +14dBm minimum • 802.11n HT40(5GHz) : +13dBm minimum 802.11ac VHT80(5GHz): +10dBm minimum • 802.11ac VHT160(5GHz) : +10dBm minimum 802.11ax HE40(2.4GHz): +12dBm minimum 802.11ax HE80(5GHz) : +10dBm minimum 802.11ax HE160(5GHz) : +10dBm minimum **Power Consumption** Transmit mode 2.0 W Receive mode 1.6 W Idle mode (PSP) 180 mW (WLAN Associated) Idle mode 50 mW (WLAN unassociated) Connected Standby 10mW Radio disabled 8 mW **Power Management** ACPI and PCI Express compliant power management 802.11 compliant power saving mode Receiver Sensitivity⁴ 802.11b, 1Mbps : -93.5dBm maximum • 802.11b, 11Mbps : -84dBm maximum 802.11a/q, 6Mbps : -86dBm maximum 802.11a/g, 54Mbps : -72dBm maximum 802.11n, MCS07 : -67dBm maximum 802.11n. MCS15 : -64dBm maximum 802.11ac, MCS0(VHT80) : -84dBm maximum 802.11ac. MCS9(VHT80) : -59dBm maximum 802.11ac, MCS9(VHT160): -58.5dBm maximum 802.11ax, MCS11(HE40): -57dBm maximum 802.11ax, MCS11(HE80): -54dBm maximum 802.11ax, MCS11(HE160): -53.5dBm maximum Antenna type High efficiency antenna with spatial diversity, mounted in the display enclosure Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth communications **Form Factor** PCI-Express M.2 MiniCard Dimensions 1. Type 2230 : 2.3 x 22.0 x 30.0 mm



QuickSpecs

	Weight	1. Type 2230 : 2.	8a
	Operating Voltage	3.3v +/- 9%	
	Temperature	Operating	14° to 158° F (–10° to 70° C)
		Non-operating	–40° to 176° F (–40° to 80° C)
	Humidity	Operating	10% to 90% (non-condensing)
		Non-operating	5% to 95% (non-condensing)
	Altitude	Operating	0 to 10,000 ft (3,048 m)
		Non-operating	0 to 50,000 ft (15,240 m)
	LED Activity		lio OFF; LED OFF – Radio ON
HP Integrated Module wit	h Bluetooth 4.0/4.1/4.2/5.0		
	Bluetooth Specification		5.1/5.2/5.3 Compliant
	Frequency Band	2402 to 2480 MH	
	Number of Available Channels	Legacy: 0~79 (1 BLE: 0~39 (2 MH;	
	Signaling Data Rate		lata rate; throughput up to 2.17 Mbps
	Signaling Data Kale		rate; throughput up to 0.2 Mbps
			nous Connection Oriented links up to 3, 64 kbps, voice
		channels	
			onous Connection Less links 2178.1 kbps/177.1 kbps H5) or 864 kbps symmetric (3-EV5)
	Transmit Power	The Bluetooth co	mponent shall operate as a Class II Bluetooth device with
		a maximum tran	smit power of + 9.5 dBm for BR and EDR.
	Power Consumption	Peak (Tx): 330 m	
		Peak (Rx): 230 m Selective Suspen	
	Bluetooth Software	-	ws Bluetooth Software
	Supported Link Topology		
	Power Management	Microsoft Windows ACPI, and USB Bus Support	
	Certifications	FCC (47 CFR) Part	t 15C, Section 15.247 & 15.249
	Power Management	ETS 300 328, ETS	
	Certifications	Low Voltage Dire	
	Bluetooth Software	UL, CSA, and CE N	
	Supported	BT4.1-ESR 5/6/7 LE Link Layer Pin	•
		LE Dual Mode	3
		LE Link Layer	
			e Directed Advertising
			tion Oriented Channels
		Train Nudging & BT4.2 ESR08 Con	
		LE Secure Conne	•
			ink Layer Privacy
		-	xtended Scanner Filter Policies
		LE Data Packet L	-
		FAX Profile (FAX) Basic Imaging Pr	
		Sustennuging FI	



Headset Profile (HSP) Hands Free Profile (HFP) Advanced Audio Distribution Profile (A2DP) BT5.2 ESR9/10 Compliance LE Advertisement Extensions Channel Selection Algo Limited High Duty Cycle Non-Connectable Advertising 2Mbps LE LE Long Range

1. Wi-Fi 6E requires a Wi-Fi 6E router, sold separately, to function in the 6GHz band. Availability of public wireless access points limited. Wi-Fi 6E is backwards compatible with prior 802.11 specs. And available in countries where Wi-Fi 6E is supported. Wi-Fi 6E is designed to support gigabit data rate when transferring files between two devices connected to the same router. Requires a wireless router, sold separately, that supports 80MHz and higher channels.

2. Check latest software/driver release for updates on supported security features.

3. The FCC has declared as of September 1, 2014 products that utilize passive scanning on channel 12/13 and are capable of transmitting must fully comply with requirements of 15.247 or otherwise disable those channels.

4. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).



Intel [®] 5G Solution 5000 ¹	Technology/Operating	WCDMA/HSPA+ operating bands:
	bands	Band 1: 1920 to 1980 MHz (UL), 2110 to 2170 MHz (DL)
		Band 2: 1850 to 1910 MHz (UL), 1930 to 1990 MHz (DL)
		Band 4: 1710 to 1755 MHz (UL), 2110 to 2155 MHz (DL)
		Band 5: 824 to 849 MHz (UL), 869 to 894 MHz (DL)
		Band 8: 880 to 915 MHz (UL), 925 to 960 MHz (DL)
		LTE FDD/TDD operating bands:
		Band 1: 1920 to 1980 MHz (UL), 2110 to 2170 MHz (DL)
		Band 2: 1850 to 1910 MHz (UL), 1930 to 1990 MHz (DL)
		Band 3: 1710 to 1785 MHz (UL), 1805 to 1880 MHz (DL)
		Band 4: 1710 to 1755 MHz (UL), 2110 to 2155 MHz (DL)
		Band 5: 824 to 849 MHz (UL), 869 to 894 MHz (DL)
		Band 7: 2500 to 2570 MHz (UL), 2620 to 2690 MHz (DL)
		Band 8: 880 to 915 MHz (UL), 925 to 960 MHz (DL)
		Band 12: 699 to 716 MHz (UL), 729 to 746 MHz (DL)
		Band 13: 777 to 787 MHz (UL), 746 to 756 MHz (DL)
		Band 14: 788 to 798 MHz (UL), 758 to 768 MHz (DL)
		Band 17: 704 to 716 MHz (UL), 734 to 746 MHz (DL)
		Band 18: 815 to 830 MHz (UL), 860 to 875 MHz (DL)
		Band 19: 830 to 845 MHz (UL), 875 to 890 MHz (DL)
		Band 20: 832 to 862 MHz (UL), 791 to 821 MHz (DL) Band 25: 1850 to 1915 MHz (UL), 1930 to 1995 MHz (DL)
		Band 26: 814 to 849 MHz (UL), 859 to 894 MHz (DL)
		Band 28: 703 to 748 MHz (UL), 758 to 803 MHz (DL)
		Band 29: 717 to 728 MHz (DL)
		Band 30: 2305 to 2315 MHz (UL) 2350 to 2360 MHz (DL)
		Band 32: 1452 to 1496 MHz (DL)
		Band 34: 2010 to 2025 MHz (UL/DL)
		Band 38: 2570 to 2620 MHz (UL/DL)
		Band 39: 1880 to 1920 MHz (UL/DL)
		Band 40: 2300 to 2400 MHz (UL/DL)
		Band 41: 2496 to 2690 MHz (UL/DL)
		Band 42: 3400 to 3600 MHZ (UL/DL)
		Band 43: 3400 to 3800 MHZ (UL/DL)
		Band 46: 5150 to 5925 MHZ (DL)
		Band 48: 3550 to 3700 MHZ (UL/DL)
		Band 66: 1710 to 1800 MHz (UL), 2110 to 2200 MHz (DL)
		Band 71: 663 to 698 MHz (UL), 617 to 652 MHz (DL)
		5GNR Sub 6GHZ
		n1: 1920 to 1980 MHz (UL), 2110 to 2170 MHz (DL) n2: 1850 to 1910 MHz (UL), 1930 to 1990 MHz (DL)
		n3: 1710 to 1785 MHz (UL), 1805 to 1880 MHz (DL)
		n5: 824 to 849 MHz (UL), 869 to 894 MHz (DL)
		n7: 2500 to 2570 MHz (UL), 2620 to 2690 MHz (DL)
		n8: 880 to 915 MHz (UL), 925 to 960 MHz (DL)
		n20: 832 to 862 MHz (UL), 791 to 821 MHz (DL)
		n25: 1850 to 1915 MHz (UL), 1930 to 1995 MHz (DL)
		n28: 703 to 748 MHz (UL), 758 to 803 MHz (DL)
		n38: 2570 to 2620 MHz (UL/DL)
		n40: 2300 to 2400 MHz (UL/DL)

Technical Specifications	
Wireless protocol star	3GPP Rel15 5G NR sub-6 LTE Rel14
	20 layers and 2 Gbps downlink (DL) throughput – 4 × 4 MIMO across 5x CA 200 Mbps/uplink (UL) throughput – 40 MHz ULCA and 256 QAM WCDMA R99, 3GPP Release 5, 6, 7 and 8 UMTS Specification
GPS	Standalone, A-GPS (MS-A, MS-B)
GPS bands	GPS: L1 (1575.42MHz) GLONASS: L1 (1602MHz) BeidouB1(1561.098MHz) Galileo E1 (1575.42) QZSS(1575.42 MHz)
Maximum data rates	SA 5G/NR sub-6 Peak: DL4.67Gbps/ UL 1.25Gbps 5G NSA sub 6G : DL: 3.8 Gbps/UL 700Mbps LTE: ue-CategoryDL 19, (DL : 1.6 Gbps) ue-CategoryUL 13 , (UL: 150Mbps) DC-HSPA+: 42 Mbps (Download), 11.5 Mbps (Upload)
Maximum output pow	
Maximum power	5G Sub 6 : 2500 mA
consumption	LTE: 1,300 mA (peak); 1100 mA (average) HSPA+: 1,100 mA (peak); 800 mA (average)
Form Factor	M.2, 3042-S3 Key B
Weight	8 g
Dimensions	52 mm × 30 mm × 2.6 mm
(Length x Width x Thic eSIM	kness) Support
1. Just all Constitute is a stimulated and south the souther	red at the factory. Madula designed for EC CA (standalane) and EC ND NCA

1. Intel[®] 5G module is optional and must be configured at the factory. Module designed for 5G SA (standalone), and 5G NR NSA (non-standalone) networks as carriers deploy Evolved-Universal Terrestrial Radio Access New Radio Dual Connectivity (ENDC) with both 100Mhz of 5G NR and LTE channel bandwidth, using 256QAM 4x4 as defined by 3GPP. Module requires activation and separately purchased service contract. Check with service provider for coverage and availability in your area. Data connection, upload and download speeds will vary due to network, location, environment, network conditions, and other factors. Backwards compatible to 4G LTE and 3G HSPA technologies. 5G module planned to be available in select platforms and select countries, where carrier supported.



Intel® XMM™ 7560 R+ LTE-Advanced Pro ¹	Technology/Operating bands	FDD LTE: 2100 (Band 1), 1900 (Band 2), 1800 (Band 3), 1700/2100 (Band 4), 850 (Band 5), 2600 (Band 7), 900 (Band 8), 700 (Band 12 lower), 700 (Band 13 upper), 700 (Band 14 upper), 700 (Band 17 lower), 850 (Band 18 lower), 850 (Band 19 upper), 800 (Band 20), 1900 (Band 25), 850 (Band 26), 700 (Band 28), 700 (Band 29 RX only), 2300 (Band 30), 1700/2100 (Band 66), 600 (band 71). TDD LTE: 2100 (Band 34), 2600 (Band 38), 1900 (Band 39), 2400 (Band 40), 2500 (Band 41), 3500 (Band 42), 3700 (Band 43), 3700 (band 48), 5200 (Band 46 RX only) MHz; HSPA+: 2100 (Band 1), 1900 (Band 2), 1700/2100 (Band 4), 850 (Band 5), 900 (Band 8) MHz
	Wireless protocol standards	3GPP Release 12 LTE Specification DL-CAT.16, DL 100MHz BW throughput up to 978Mbps; UL-CAT.13 40MHz throughput up to 150Mbps WCDMA R99, 3GPP Release 5, 6, 7 and 8 UMTS Specification
	GPS	Standalone GPS/Beidou/Glonass, A-GPS (MS-A, MS-B)
	GPS bands	1575.42 MHz ± 1.023 MHz, GLONASS 1596-1607MHz, Beidou 1561.098 MHz
	Maximum data rates	LTE: 978 Mbps (Download), 150 Mbps (Upload) DC-HSPA+: 42 Mbps (Download), 5.76 Mbps (Upload) HSPA+: 21Mbps (Download), 5.76 Mbps (Upload)
	Maximum output power	LTE: 23 dBm in all band except B41 LTE B41 HPUE = 26dBm HSPA+: 23.5 dBm
	Maximum power consumption	LTE: 1,200 mA (peak); 900 mA (average) HSPA+: 1,100 mA (peak); 800 mA (average)
	Form Factor	M.2, 3042-S3 Key B
	Weight	6 g
	Dimensions (Length x Width x Thickness)	42 x 30 x 2.3 mm
	eSIM	Support

1. Mobile Broadband is an optional feature. Connection requires wireless data service contract, network support, and is not available in all areas. Contact service provider to determine the coverage area and availability. Connection speeds will vary due to location, environment, network conditions, and other factors. 4G LTE not available on all products or in all countries.



QuickSpecs

Near Field Communications Controller (optional)	Dimensions (L x W x H) Chipset System interface NFC RF standards	Module 25 mm by 10 mm by 2.0 mm NPC100 I2C ISO/IEC 14443 A ISO/IEC 14443 B ISO/IEC 15693 ISO/IEC 18092 ECMA-340 NFCIP-1 Target and Initiator ECMA-320 NFCIP-2
	NFC Forum Support	Tag Type 1, Type 2, Type3 and Type 4, NFCIP-1 and NFCIP-2
	Reader (PCD-VCD) Mode	ISO/IEC 14443 A ISO/IEC 14443 B ISO/IEC 15693 MIFARE 1K MIFARE 4K MIFARE DESFire FeliCa Jewel and Topaz cards
	Card Emulation (PICC- VICC) Mode	ISO/IEC 14443 A ISO/IEC 14443 B and B' MIFARE FeliCa
	Frequency	13.56 MHz
	NFC Modes Supported	Reader/Writer, Peer-to-Peer
	Raw RF Data Rates	106, 212, 424, 848 kbps
	Operating temperature	0°C to 70°C
	Storage temperature	-20°C to 125°C
	Humidity	10-90% operating 5-95% non-operating
	Supply Operating voltage	4.35 to 5.25 Volts
	I/O Voltage	1.8V or 3.3V
	Power Consumption (Booster enable, VBAT= 3	.3V, VCC_BOOST = 5V)
	Mode	Power Consumption, Typical
	Polling	7.3 mA
	Detected Test Tag Type 1	Total 283.8 mA Net Module 236.8 mA
	Detected Test Tag Type 2	Total 288.8 mA Net Module 241.8 mA
	Detected Test Tag Type 3	Total 287.7 mA Net Module 240.7 mA
	Detected Test Tag Type 4	Total 282.3 mA Net Module 235.3 mA
	Antenna	Antenna connector, 0.5mm pitch, 7 connector FPC. Antenna matching is external to module.



POWER

1. Actual battery Watt-hours (Wh) will vary from design capacity. Battery capacity will naturally decrease with shelf life, time, usage, environment, temperature, system configuration, loaded apps, features, power management settings and other factors

AC Adapter 45 Watt nPFC	Dimensions (H x W x D)	94.0mm x 40.0mm x 26.5	mm	
Standard USB type C Straight 1.8m	Weight	192.5g +/-10%		
Straignt 1.8m	Input	Input Efficiency	Average Efficiency of 25%, 50%, 75%, 100% load condition with 115Vac/230Vac Spec: 5V : 81.5% 9V : 86.7% 12V : 87.41% 15V : 87.8%	
		Input frequency range	47 ~ 63Hz	
		Input AC current	Max. 1.4 A at 90 Vac	
	Output	Output power	5V/15W 9V/27W 12V/36W 15V/45W	
		DC output	5V/9V/12V/15V	
		Hold-up time	5ms at 115 Vac input	
		Output current limit	<5.0A	
	Connector	C6		
	Environmental Design	Operating temperature	32°F to 95°F (0° to 35°C)	
		Non-operating (storage) temperature	-4°F to 185°F (-20° to 85°C)	
		Altitude	0 to 16,400 ft (0 to 5000m)	
		Humidity	20% to 95%	
		Storage Humidity	10% to 95%	
	EMI and Safety Certifications	Eg: *CE Mark - full compliance with LVD and EMC directives * Worldwide safety standards - IEC60950-1 and/or IEC62368-1, EN60950-1 and/or EN62368-1, UL60950-1 and/or UL62368-1, Class1, SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55032 Class B, FCC Class B, CISPR32 Class B, CCC, NOM-001 NYCE. * MTBF - over 200,000 hours at 25°C ambient condition.		
AC Adapter 65 Watt nPFC	Dimensions (H x W x D)	88 x 53.5 x 21mm		
Slim USB type C Straight	Weight	unit: 220g +/- 10g		
1.8m	Input	Input Efficiency	81.5% min at 115 Vac/ 230Vac @ 5V/3A 86.7% min at 115 Vac/ 230Vac @ 9V/3A 88% min at 115 Vac/ 230Vac @ 12V/5A 89% min at 115 Vac/ 230Vac @ 15V/4.33A 89% min at 115 Vac/ 230Vac @ 20V/3.25A	
		Input frequency range	47 ~ 63 Hz	
		Input AC current	1.6 A at 90 VAC and maximum load	



Technical Specifi	cations			
	Output	Output power	65W	
		DC output	5V/9V/12V/15V/20V	
		Hold-up time	5ms at 115 Vac input	
		Output current limit	<8.0A	
	Connector	C6		
	Environmental Design	Operating 32°F to 95°F (0° to 35°C) temperature		
		Non-operating (storage) temperature	-4°F to 185°F (-20° to 85°C)	
		Altitude	0 to 16,400 ft (0 to 5000m)	
		Humidity	5% to 95%	
		Storage Humidity	5% to 95%	
	EMI and Safety Certifications	Eg: *CE Mark - full compliance with LVD and EMC directives * Worldwide safety standards - IEC60950-1 and/or IEC62368-1, EN60950-1 and/or EN62368-1, UL60950-1 and/or UL62368-1, Cl SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55032 Class B, F Class B, CISPR32 Class B, CCC, NOM-001 NYCE. * MTBF - over 200,000 hours at 25°C ambient condition.		
AC Adapter 65 Watt nPFC	Dimensions (H x W x D)	90.0mm x 51.0mm x 28.5	mm	
Standard USB type C	Weight	250g +/-10%		
Straight 1.8m	Input	Input Efficiency	Average Efficiency of 25%, 50%, 75%, 100% load condition with 115Vac/230Vac Spec: 5V : 81.5% 9V : 86.7% 12V : 88% 15V : 88% 20V : 89%	
		Input frequency range	47 ~ 63Hz	
		Input AC current	Max. 1.6 A at 90 Vac	
	Output	Output power	5V/15W 9V/27W 12V/60W 15V/60W 20V/65W	
		DC output	5V/9V/12V/15V/20V	
		Hold-up time	5ms at 115 Vac input	
		Output current limit	<8.0A	
	Connector	C6		
	Environmental Design	Operating temperature	32°F to 95°F (0° to 35°C)	
		Non-operating (storage) temperature	-4°F to 185°F (-20° to 85°C)	



Technical Specifications Altitude 0 to 16,400 ft (0 to 5000m) Humidity 20% to 95% **Storage Humidity** 10% to 95% **EMI and Safetv** Ea: Certifications *CE Mark - full compliance with LVD and EMC directives * Worldwide safety standards - IEC60950-1 and/or IEC62368-1. EN60950-1 and/or EN62368-1, UL60950-1 and/or UL62368-1, Class1, SELV: Agency approvals - C-UL-US, NORDICS, DENAN, EN55032 Class B, FCC Class B, CISPR32 Class B, CCC, NOM-001 NYCE. * MTBF - over 200,000 hours at 25°C ambient condition. HP 100W+10W Slim USB- Dimensions (H x W x D) 136 x 60 x 22mm C+USB-A Straight AC Weight unit: 365a +/- 10a **Power Adapter Kenting** Input Input Efficiency Average Efficiency of 25%, 50%, 75%, 100% load condition with 115Vac/230Vac Spec: 5VusbA:73.62% 5VusbC: 81.5% 9V:86.7% 12V:88% 15V:89% 20V:89% > 90% efficiency at 100W (20V/5A) output condition Input frequency range 47~63 Hz **Input AC current** 1.6 A at 90 VAC and maximum load Output **Output power** 110W **DC** output 5VusbA/5V/9V/12V/15V/20V Hold-up time 5ms at 115 Vac input **Output current limit** <6.25A C6. USB Type C Connector 32°F to 95°F (0° to 35°C) **Environmental Design** Operating temperature Non-operating (storage) -4°F to 185°F (-20° to 85°C) temperature Altitude 0 to 16,400 ft (0 to 5000m) Humidity 5% to 95% **Storage Humidity** 5% to 95% **EMI and Safety** Eq: Certifications *CE Mark - full compliance with LVD and EMC directives * Worldwide safety standards - IEC60950-1 and/or IEC62368-1, EN60950-1 and/or EN62368-1, UL60950-1 and/or UL62368-1, Class1, SELV: Agency approvals - C-UL-US, NORDICS, DENAN, EN55032 Class B, FCC Class B. CISPR32 Class B. CCC. NOM-001 NYCE. * MTBF - over 200,000 hours at 25°C ambient condition.



QuickSpecs

Technical Specifications

HP 3-cell Long Life Li-Ion (51 Wh) ¹	Dimensions (H x W x D) Weight	251.8 x 70.3 x 6.82mm (9.91 x 2.77 x 0.27 inch) 0.229kg +/- 10g (0.505 lb)		
	-	3cell Lithium-Ion Polymer cell / 566075		
	Cells/Type -	-		
	Energy	Voltage	11.58V	
		Amp-hour capacity	4.431Ah	
		Watt-hour capacity ¹	51.3Wh	
	Temperature	Operating (Charging)	32° to 113° F (0° to 45° C)	
		Operating (Discharging)	14° to 140° F (-10° to 60° C)	
		Fuel Gauge LED	NA	
		Warranty	Follow product spec	
		Optional Travel Battery	No	
		Available	1.04	
	Weight	303.2 x 90.1 x 6.82mm (1 0.357kg +/- 10g (0.787 lb)	
	Weight Cells/Type	303.2 x 90.1 x 6.82mm (1 0.357kg +/- 10g (0.787 lb 6cell Lithium-Ion Polymer) r cell / 564975	
	Weight	303.2 x 90.1 x 6.82mm (1 0.357kg +/- 10g (0.787 lb 6cell Lithium-Ion Polymer Voltage) r cell / 564975 11.58V	
	Weight Cells/Type	303.2 x 90.1 x 6.82mm (1 0.357kg +/- 10g (0.787 lb 6cell Lithium-Ion Polymer Voltage Amp-hour capacity) r cell / 564975 11.58V 6.565Ah	
HP 6-cell Long Life Li-Ion (76Wh) ¹	Weight Cells/Type Energy	303.2 x 90.1 x 6.82mm (1 0.357kg +/- 10g (0.787 lb 6cell Lithium-Ion Polymer Voltage Amp-hour capacity Watt-hour capacity ¹) r cell / 564975 11.58V 6.565Ah 76Wh	
	Weight Cells/Type	303.2 x 90.1 x 6.82mm (1 0.357kg +/- 10g (0.787 lb 6cell Lithium-Ion Polymer Voltage Amp-hour capacity Watt-hour capacity ¹ Operating (Charging)) r cell / 564975 11.58V 6.565Ah 76Wh 32° to 113° F (0° to 45° C)	
	Weight Cells/Type Energy	303.2 x 90.1 x 6.82mm (1 0.357kg +/- 10g (0.787 lb 6cell Lithium-Ion Polymer Voltage Amp-hour capacity Watt-hour capacity ¹ Operating (Charging) Operating (Discharging)) r cell / 564975 11.58V 6.565Ah 76Wh	
	Weight Cells/Type Energy	303.2 x 90.1 x 6.82mm (1 0.357kg +/- 10g (0.787 lb 6cell Lithium-Ion Polymer Voltage Amp-hour capacity Watt-hour capacity ¹ Operating (Charging)) r cell / 564975 11.58V 6.565Ah 76Wh 32° to 113° F (0° to 45° C)	
	Weight Cells/Type Energy	303.2 x 90.1 x 6.82mm (1 0.357kg +/- 10g (0.787 lb 6cell Lithium-Ion Polymer Voltage Amp-hour capacity Watt-hour capacity ¹ Operating (Charging) Operating (Discharging)) cell / 564975 11.58V 6.565Ah 76Wh 32° to 113° F (0° to 45° C) 14° to 140° F (-10° to 60° C)	



AUDIO

HD Stereo Codec	Realtek ALC3315
Audio I/O Ports	Headset: CTIA only and Headphone-out
Internal Speaker Amplifier	Cirrus Logic High-Efficiency Boosted Class D Amplifier
Multi-streaming Capable	Playback multi-streaming can be enabled in the audio control panel to allow independent audio.
	Following MSFT Behaviour
Sampling	DAC: 44.1k/48kHz
	ADC: 48kHz
Wavetable Syntheses	
Analog Audio	Support 3.5mm Headset: CTIA only and Headphone-out
# of Channels on Line-Out	
Internal Speaker	Yes

FINGERPRINT READER

Sensor vendor	Main source : Synaptics FS7605
	2nd source : ELAN 80SW
Sensor type	Capacitive
DPI resolution	Main source : 363 DPI
	2nd source : 508 DPI
Scan area	Main source : 7.4x6mm sensor area
	2nd source : 80x80 pixels
False Rejection Rate	Main source: <1%
	2nd source : FRR=≤ 3%
False Acceptance Rate	Main source : FAR 1:50K FAR
	2nd source : < 0.001%
Mobile Voltage Operation	Main source : 3.0V to 3.6V
	2nd source : 2.7V~3.6V
Operating Temperature	Main source : 0°C~60°C
	2nd source : -20°C - +80°C
Current Consumption	Main source : 100mA max
Image	2nd source : 35mA peak
Low Latency Wait For	Main source : 260uA
Finger	2nd source : 300uA
Capture Rate	Main source:<30msec per image
	2nd source : 50 frame/sec
ESD Resistance	IEC 61000-4-2 4B (+15KV)
Detection Matrix	Main source : 363 dpi / 7.4x6mm sensor area
	2nd source : 508 dpi / 4x4mm sensor area



ENVIRONMENTAL DATA

ENVIKONMENTAL DATA Eco-Label Certifications &		or is in the process of heing	certified to the following approvals and		
declarations	This product has received or is in the process of being certified to the following approvals and may be labeled with one or more of these marks:				
	IT ECO declaration				
			MP)		
		y Management Program (FE			
	-		See http://www.epeat.net for registration		
	status in your country.				
	TCO Certified				
		servation Program (CECP)			
		onmental Protection Admini	stration (SEPA)		
	Taiwan Green Ma	rk			
	Korea Eco-label				
	Japan PC Green la				
Sustainable Impact	Ocean-bound plastic in S	•			
Specifications	• 55% post-consumer recy	/cled plastic			
	 Low halogen 				
	-		ainably sourced and recyclable		
			inably sourced and recyclable		
	Bulk packaging available				
System Configuration	-	57 1	nd Declared Noise Emissions data for the		
	Notebook model is based	on a "Typically Configured N	otebook".		
			1		
Energy Consumption					
(in accordance with US					
ENERGY STAR® test					
method)	115VAC, 60Hz	230VAC, 50Hz	100VAC, 50Hz		
Normal Operation (Sort					
idle)	5.71 W	6.14 W	5.89 W		
Normal Operation (Long					
idle)	1.14 W	1.28 W	1.23 W		
Sleep	1.14 W	1.28 W	1.23 W		
Off	0.42 W	0.44 W	0.42 W		
	NOTE:				
	Energy efficiency data listed is for an ENERGY STAR® compliant product if offered within the				
	model family. HP computers marked with the ENERGY STAR® Logo are compliant with the				
	applicable U.S. Environmental Protection Agency (EPA) ENERGY STAR® specifications for				
	computers. If a model family does not offer ENERGY STAR® compliant configurations, then				
	energy efficiency data listed is for a typically configured PC featuring a hard disk drive, a high				
	efficiency power supply, and a Microsoft Windows® operating system.				
Heat Dissipation*	115VAC, 60Hz	230VAC, 50Hz	100VAC, 50Hz		
Normal Operation (Short					
idle)	19.5 BTU/hr	21 BTU/hr	20.1 BTU/hr		
Normal Operation (Long					
idle)	3.9 BTU/hr	4.4 BTU/hr	4.2 BTU/hr		
Sleep	3.9 BTU/hr 1.4 BTU/hr	4.4 BTU/hr 1.5 BTU/hr	4.2 BTU/hr 1.4 BTU/hr		



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Technical Specifications

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	* NOTE: Heat attained for		ed on the measured watts, as	suming the service level is
Declared Noise Emissions		Sound Power	Sound P	ressure
(in accordance with ISO 7779 and ISO 9296)		(L _{WAd} , bels)	(L _{pAm} , de	ecibels)
Typically Configured – Idle	2.3 16.1			
Fixed Disk – Random writes		2.5	17.	
Optical Drive – Sequential reads	3.2 22.9			
Longevity and Upgrading		This product can be upgraded, possibly extending its useful life by several years. Upgradeable features and/or components contained in the		
	Spare parts a of production	-	warranty period and or for up	to "5" years after the end
Additional Information	 This product is in compliance with the Restrictions of Hazardous Substances (RoHS) directive - 2011/65/EC. This HP product is designed to comply with the Waste Electrical and Electronic 			
	• This	 Drinking Water and Toxic Enforcement Act of 1986). This product is in compliance with the IEEE 1680 (EPEAT) standard at the Gold level, see www.epeat.net 		
	• This www			
	 Iso1043. This product is 3.5% recycle-able when properly disposed of at end of life. 			
Packaging Materials	External:	PAPER/Corrugated		287 g
		PAPER/Paperboard		72 g
		PAPER/Paper		4 g
		PAPER/Molded Pulp		162 g
	Internal:	PLASTIC/Polyethylene lov	v density - LDPE	13 g
	The plastic packaging material contains at least 0.0% recycled content.			
	The corrugated paper packaging materials contains at least 51.8% recycled content.			
RoHS Compliance	HP Inc. complies fully with materials regulations. We were among the first companies to extend the restrictions in the European Union (EU) Restriction of Hazardous Substances (RoHS) Directive to our products worldwide through the HP GSE. HP has contributed to the development of related legislation in Europe, as well as China, India, and Vietnam.			
We believe the RoHS directive and similar laws play an important role in promoting elimination of substances of concern. We have supported the inclusion of additiona substances—including PVC, BFRs, and certain phthalates—in future RoHS legislati pertains to electrical and electronics products.			of additional	
			e worldwide compliance with oducts by July 2013, and we w	



	scope of the commitment to include further restricted substances as regulations continue to evolve.
	To obtain a copy of the HP RoHS Compliance Statement, see HP RoHS position statement.
Material Usage	This product does not contain any of the following substances in excess of regulatory limits (refer to the HP General Specification for the Environment at http://www.hp.com/hpinfo/globalcitizenship/environment/supplychain/gen_specifications.html): Asbestos Certain Azo Colorants Certain Brominated Flame Retardants – may not be used as flame retardants in plastics Cadmium Chlorinated Hydrocarbons Chlorinated Paraffins Bis(2-Ethylhexyl) phthalate (DEHP) Benzyl butyl phthalate (DBP) Dibutyl phthalate (DBP) Pormaldehyde Halogenated Diphenyl Methanes Lead carbonates and sulfates Lead and Lead compounds Mercuric Oxide Batteries Nickel – finishes must not be used on the external surface designed to be frequently handled or carried by the user.
Packaging Usage	 HP follows these guidelines to decrease the environmental impact of product packaging: Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in
	 Eliminate the use of neavy metals such as lead, chromium, mercury and cadmium in packaging materials. Eliminate the use of ozone-depleting substances (ODS) in packaging materials.
	 Design packaging materials for ease of disassembly. Maximize the use of post-consumer recycled content materials in packaging materials. Use readily recyclable packaging materials such as paper and corrugated materials. Reduce size and weight of packages to improve transportation fuel efficiency. Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards.



End-of-life Management and Recycling	 HP offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to: http://www.hp.com/go/reuse-recycle or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner. The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is posted on the Hewlett Packard web site at: http://www.hp.com/go/recyclers. These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM customers who integrate and re-sell HP equipment. 	
HP, Inc. Corporate Environmental Information	For more information about HP's commitment to the environment: Global Citizenship Report http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html Eco-label certifications http://www8.hp.com/us/en/hp-information/environment/ecolabels.html ISO 14001 certificates: http://h20195.www2.hp.com/V2/GetDocument.aspx?docname=c04755842 and http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf	
footnotes	 Percentage of ocean-bound plastic contained in each component varies by product Recycled plastic content percentage is based on the definition set in the IEEE 1680.1-2018 standard. External power supplies, WWAN modules, power cords, cables and peripherals excluded. 100% outer box packaging and corrugated cushions made from sustainably sourced certified and recycled fibers. Fiber cushions made from 100% recycled wood fiber and organic materials. 	

COUNTRY OF ORIGIN

China



DOCKING (Sold Separately) Docking station model #1	HP Thunderbolt Dock G2
Total number of supported displays	4
(incl. the notebook display)	
Max.resolutions supported	Dual 4K @30Hz or dual 4K UHD @ 60Hz is supported
	Single 8K@ 30Hz (multiple tiles) for Thunderbolt hosts
Dock Connectors	Non-TBT hosts DP 1.4 in high res mode (1) 8K video single cable@30Hz [10]
Technical limitations	2xDP, 1xVGA, 1xTB, 1xUSB-C alt-mode Thunderbolt Hosts:
r et mitations	Maximum of (4) displays with maximum resolution of 5K@ 30Hz running Thunderbolt host.
	Max resolution possible is dual 8K displays @ 60Hz running Thunderbolt host or running a non-Thunderbolt host in High Resolution mode @30Hz
	Non-Thunderbolt hosts:
	The highest resolution for dual displays running a non-Thunderbolt host in multi-function mode is
	(1) 5K dual cable (using both DP ports) +(1) 4K on USB-C DP port
	Non-Thunderbolt hosts support (3) displays with a max resolution of: (2) 5K single sphere (1) 4K HUD @ COULT in high resolution mode. In multi-function
	single cable + (1) 4K UHD @ 60 Hz in high resolution mode. In multi-function mode the maximum resolution for (3) displays is (2) 5K single cable @ 30Hz +
	(1) 4K UHD @ 30Hz.
Docking station model #2	HP USB-C Dock G5
Total number of supported displays	
(incl. the notebook display)	3
Max. resolutions supported	Dual 5K@ 30Hz + (1) 4K UHD (multi-function mode) [10]
Dock Connectors	1xHDMI, 2xDP
Technical limitations	Highest resolution with dual displays is two 8K@ 60Hz host in High Resolution mode.
	Three maximum displays supported are two 5K@ 30 Hz on DP ports plus one 4K UHD@ 30 Hz on HDMI in multi-function mode
	The highest resolution for a non-Thunderbolt host in Multi-function mode is a single 5K dual cable (using both DP ports) + (1) 4K on HDMI port.
Docking station model #3	HP USB-C/A Universal Dock G2
Total number of supported displays (incl. the notebook display)	3
Max. resolutions supported	Triple 4K UHD@ 60Hz [10]
Dock Connectors	1xHDMI, 2xDP
Technical limitations	The best resolution for dual or triple displays is 4K UHD@ 60Hz. For use with the USB-A adapter that comes in the box the maximum number of displays supported is (2) 4k x 60 Hz on the Type-A Gen 1 connection from the host
Docking station model #4	HP Thunderbolt 120W G4 Dock
Total number of supported displays	4
(incl. the notebook display)	7
Max.resolutions supported	Quad 4K @60Hz



	Dual 8K single cable@30 for TB hosts or USB-C hosts DP 1.4 with DSC in high res mode
Dock Connectors	2xDP, 1xHDMI, 1xTB, 1xUSB-C Alt Mode
Technical limitations	Maximum resolution and display support is dependent on the maximum capability of the notebook. Thunderbolt Hosts:
	Maximum of (4) displays with maximum resolution of 5K@ 30Hz running Thunderbolt host.
	Maximum resolution possible is dual 8K displays @ 60Hz running Thunderbolt host or running a non-Thunderbolt host in high resolution mode @30Hz Non-Thunderbolt hosts:
	The highest resolution for dual displays running a non-Thunderbolt host in multifunction mode is (1) 5K dual cable (using both DP ports) +(1) 4K on USB-C DP port
	Non-Thunderbolt hosts support (3) displays with a maximum resolution of (2) 5K single cable + (1) 4K UHD @ 60 Hz in high resolution mode. In multi-function mode the maximum resolution for (3) displays is (2) 5K single cable @ 30Hz + (1) 4K UHD @ 30Hz.
Docking station model #5	HP Thunderbolt 280W G4 Dock
Total number of supported displays (incl. the notebook display)	4
Max.resolutions supported	Quad 4K @60Hz Dual 8K single cable@30 for TB hosts or USB-C hosts DP 1.4 with DSC in high res mode
Dock Connectors	2xDP, 1xHDMI, 1xTB, 1xUSB-C Alt Mode
Technical limitations	Maximum resolution and display support is dependent on the maximum capability of the notebook.
	Thunderbolt Hosts: Maximum of (4) displays with maximum resolution of 5K@ 30Hz running Thunderbolt host.
	Maximum resolution possible is dual 8K displays @ 60Hz running Thunderbolt host or running a non-Thunderbolt host in high resolution mode @30Hz Non-Thunderbolt hosts:
	The highest resolution for dual displays running a non-Thunderbolt host in multifunction mode is (1) 5K dual cable (using both DP ports) +(1) 4K on USB-C DP port
	Non-Thunderbolt hosts support (3) displays with a maximum resolution of (2) 5K single cable + (1) 4K UHD @ 60 Hz in high resolution mode. In multi-function mode the maximum resolution for (3) displays is (2) 5K single cable @ 30Hz +
	(1) 4K UHD @ 30Hz



QuickSpecs

Туре	Description	Part Number
Audio	HP Wired USB-A Stereo Headset	428K6AA
	HP Wired 3.5mm Stereo Headset	428K7AA
Cases	HP Executive 15.6 Backpack	6KD07AA
	HP Executive 15.6 Top Load	6KD06AA
	HP Prelude G2 15.6 Backpack	1E7D6AA
	HP Prelude G2 15.6 Top Load	1E7D7AA
	HP Prelude Pro Recycled 15.6 Backpack	1X644AA
	HP Prelude Pro Recycled 15.6 Top Load	1X645AA
	HP Renew Business 17.3 Laptop Backpack	3E2U5AA
	HP Renew Business 17.3 Laptop Bag	3E2U6AA
	HP Renew Business 15.6 Laptop Bag	3E5F8AA
Docking	HP Thunderbolt 120W G2 Dock	2UK37AA
-	HP Thunderbolt 120W G2 Dock w/Audio	3YE87AA
	HP Thunderbolt 230W G2 Dock w/Combo Cable	3TR87AA
	HP USB-C 120W G5 Dock	5TW10AA
	HP USB-C/A 120W G2 Universal Dock	5TW13AA
Hub	HP USB-C Mini Dock	1PM64AA
	HP Universal USB-C Multiport Hub	50H55AA
	HP USB-C Travel Dock G2	7PJ38AA
	HP USB-C to USB-A Hub	Z6A00AA
Adapter	HP USB-C to RJ45 Adapter G2	4Z527AA
	HP USB 3.0 to Gigabit RJ45 Adapter G2	4Z7Z7AA
	HP HDMI to DVI Adapter	F5A28AA
	HP HDMI to VGA Adapter	H4F02AA
	HP USB to Gigabit RJ45 Adapter	N7P47AA
	HP USB-C to DisplayPort Adapter	N9K78AA
	HP USB-C to HDMI 2.0 Adapter	1WC36AA
	HP USB-C to RJ45 Adapter	V7W66AA
	HP USB-C to USB 3.0 Adapter	N2Z63AA
	HP USB-C to VGA Adapter	N9K76AA
Keyboard/Combo	HP 975 USB+BT Dual-Mode Wireless Keyboard	3Z726AA
	HP 455 Programmable Wireless Keyboard	4R177AA
	HP 125 WD USB Keyboard	266C9AA
	HP 320K WD USB Keyboard	9SR37AA
	HP 655 Wireless Keyboard and Mouse Combo	4R009AA
	HP 225 Wired Mouse and Keyboard Combo	286J4AA
	HP 235 Wireless Mouse and Keyboard Combo	1Y4D0AA
	HP Slim Wireless Keyboard and Mouse	T6L04AA



	HP Wired Desktop 320MK Mouse and Keyboard	9SR36AA
	HP Wireless Rechargeable 950MK Mouse and Keyboard	3M165AA
Mouse	HP USB Premium Wireless Mouse	1JR31AA
	HP 435 Multi-Device Wireless Mouse	3B4Q5AA
	HP 125 USB-A Wired Mouse	265A9AA
	HP 128 USB Laser Wired Mouse	265D9AA
	HP 320M USB-A Wired Mouse	9VA80AA
	HP Creator USB-A+Bluetooth 935 Wireless Mouse Black	1DOK8AA
	HP USB-A+Bluetooth Multi-Device 635 Wireless Mouse Black	1D0K2AA
	HP USB-A+Bluetooth Travel Bluetooth Mouse	6SP30AA
Power	HP 65W USB-C Auto Chevy AC Power Adapter	5TQ76AA
	HP 45W USB-C G2 Zeus AC Power Adapter	1HE07AA
	HP 45W USB-C LC Dali AC Power Adapter	1MZ01AA
	HP 65W USB-C Hades AC Power Adapter	1HE08AA
	HP 65W USB-C LC AC Power Adapter	1P3K6AA
	HP 65W USB-C Travel Slim Kermit AC Power Adapter	3PN48AA
Commodity	HP USB DVD-Writer EXT ODD	F2B56AA
	HP Nano Keyed Cable Lock	1AJ39AA
	HP Nano Master Keyed Cable Lock	1AJ40AA
	HP SureKey Standard/Nano/Wedge Cable Lock	6UW42AA
Memory	HP 8GB DDR5 4800 SODIMM Memory	5S4C3AA
	HP 16GB DDR5 4800 SODIMM Memory	5S4C4AA
	HP 32GB DDR5 4800 SODIMM Memory	5S4C0AA



Change Log

V1 to V2		Description of change:
	Updated	Function Keys section; added note in Manageability feature
V2 toV3	Updated	Memory in Options and Accessories sections
V3 to V4	Removed	Tile App
V4 to V5	Updated	Bluetooth version
V5 to V6	Updated	Windows OS
V6 to V7	Updated	At a Glance section MIL-STD testing
V7 to V8	Updated	Operating Systems
V8 to V9	Updated	eSim support on Intel 5000 5G Solution, added Thunderbolt Dock G4
V9 to V10	Updated	Networking and communication section
V10 to V11	Updated	DisplayPort ™ in Display section
V11 to V12	Updated	Storage and Drives section
V12 to V13	Updated	Intel [®] 5G Solution 5000 disclaimer
V13 to V14	Added	Fingerprint Reader Section
	V4 to V5 V5 to V6 V6 to V7 V7 to V8 V8 to V9 V9 to V10 V10 to V11 V11 to V12 V12 to V13	V4 to V5UpdatedV5 to V6UpdatedV6 to V7UpdatedV7 to V8UpdatedV8 to V9UpdatedV9 to V10UpdatedV10 to V11UpdatedV11 to V12UpdatedV12 to V13Updated

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